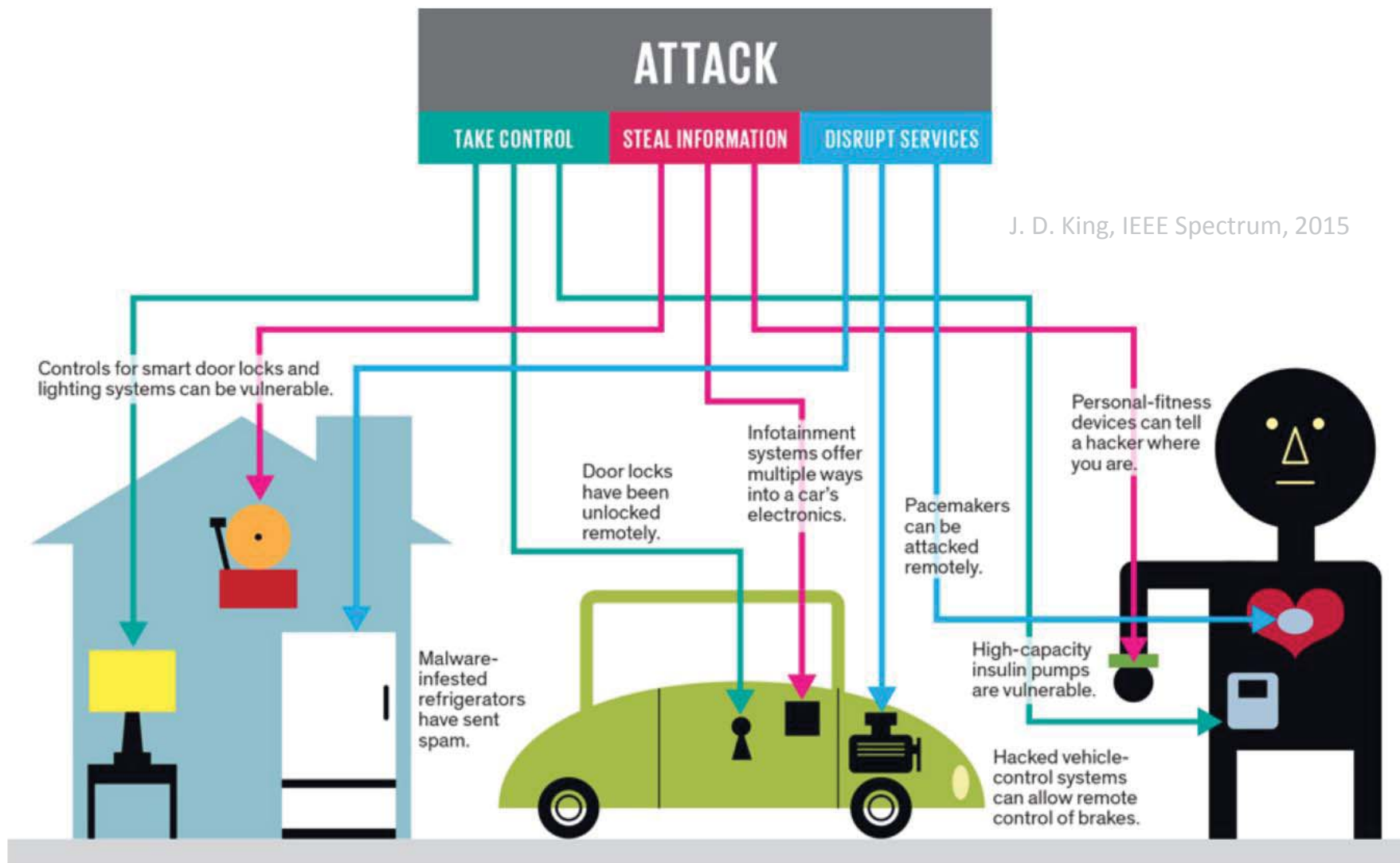


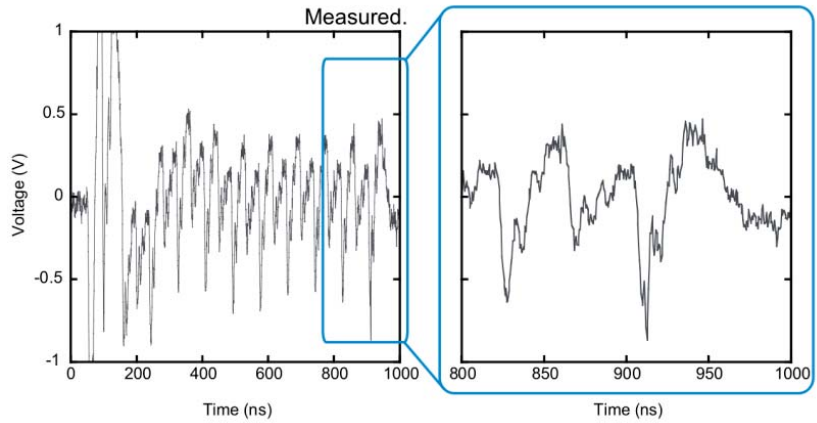
# Hardware Security for and beyond CMOS Technology

Johann Knechtel  
johann@nyu.edu  
wp.nyu.edu/johann

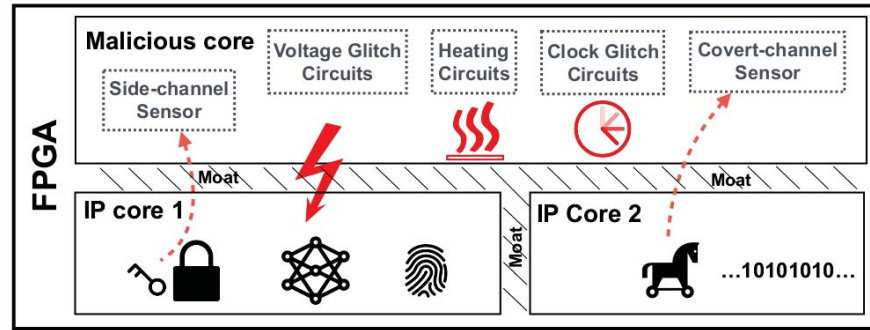
International Symposium on Physical Design – Online, March 24, 2021



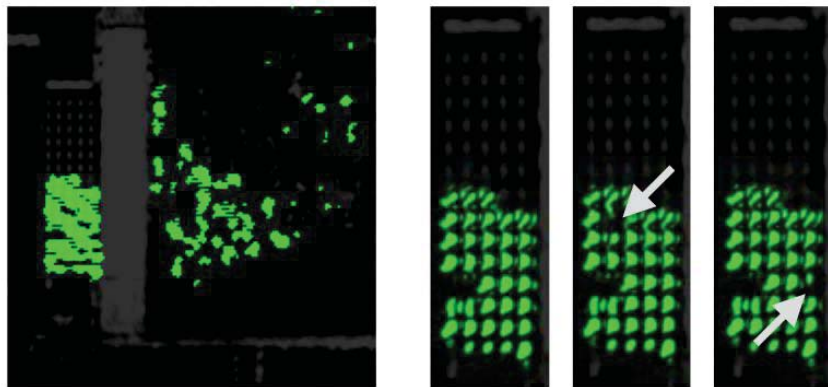
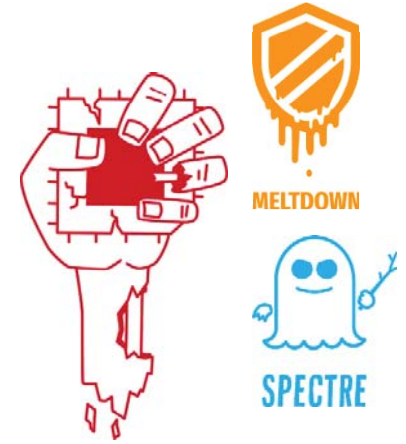
# Data and Computation at Risk – Right at the Hardware



Fujimoto et al., EMC 2014

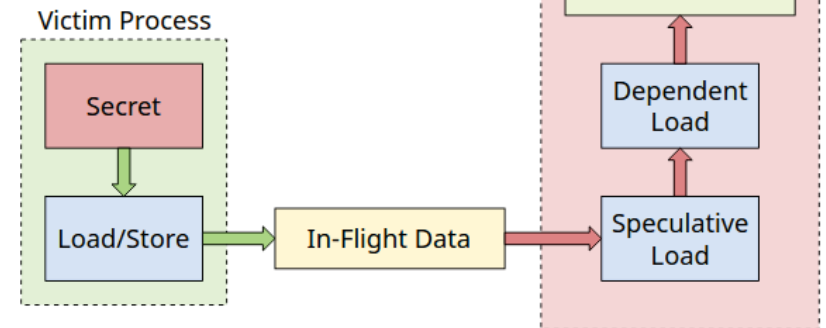


Alam et al., FDTC 2019

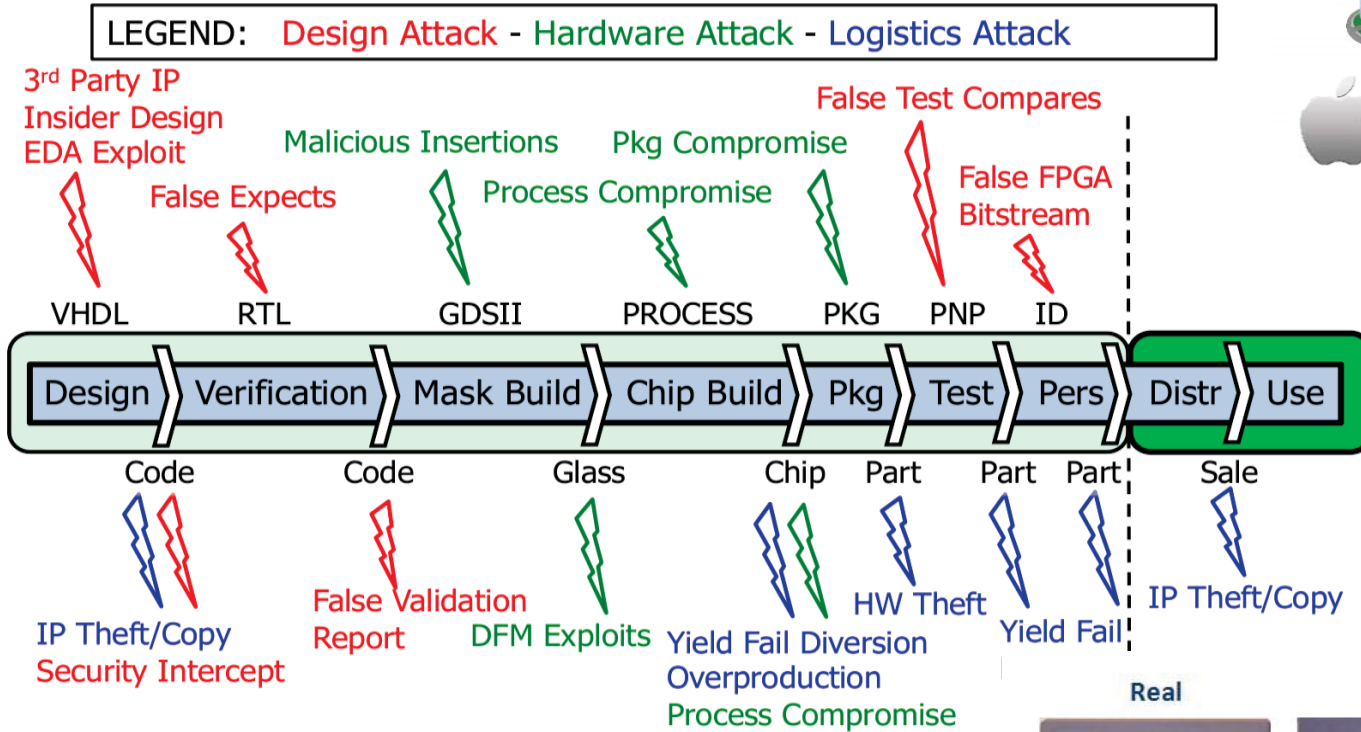


Tajik et al., CCS, 2017

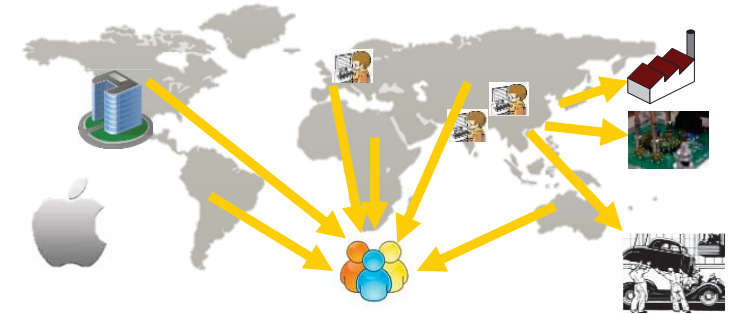
<https://www.bleepingcomputer.com>, 2019



# Hardware Itself Also at Risk



Kerry Bernstein, DARPA, 2016

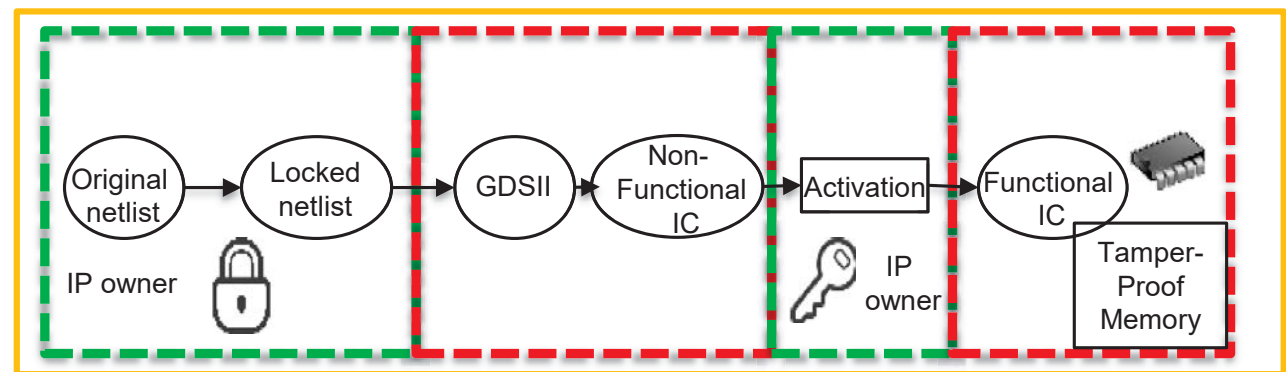
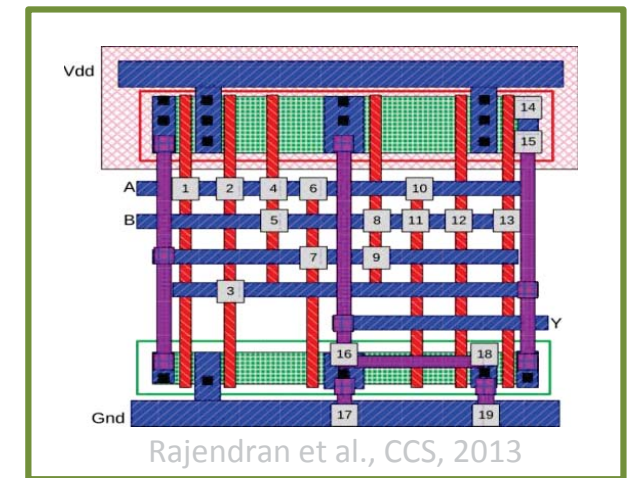
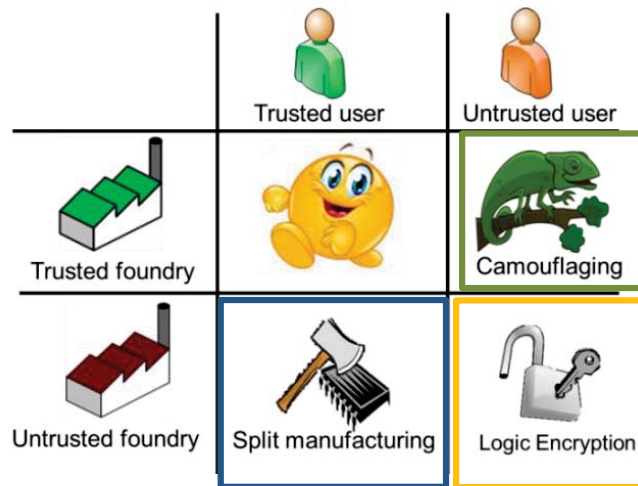
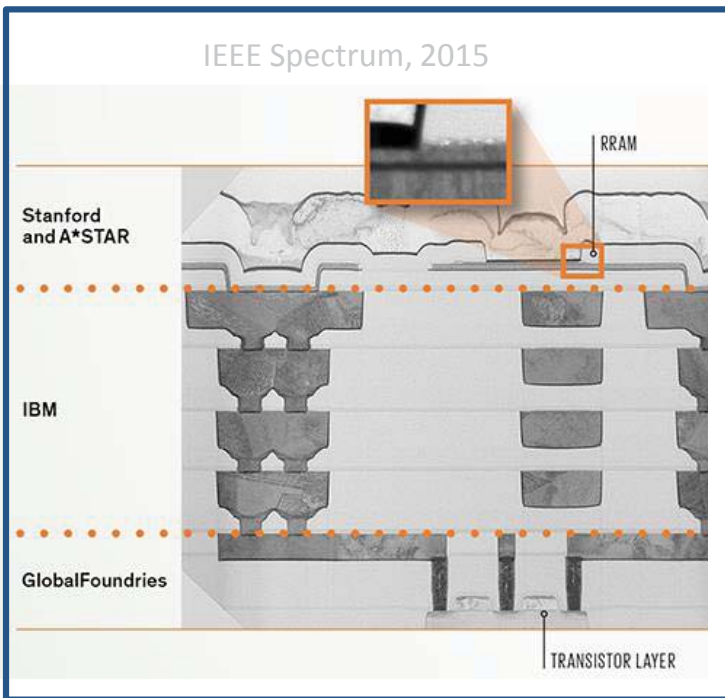


IEEE Spectrum, 2015



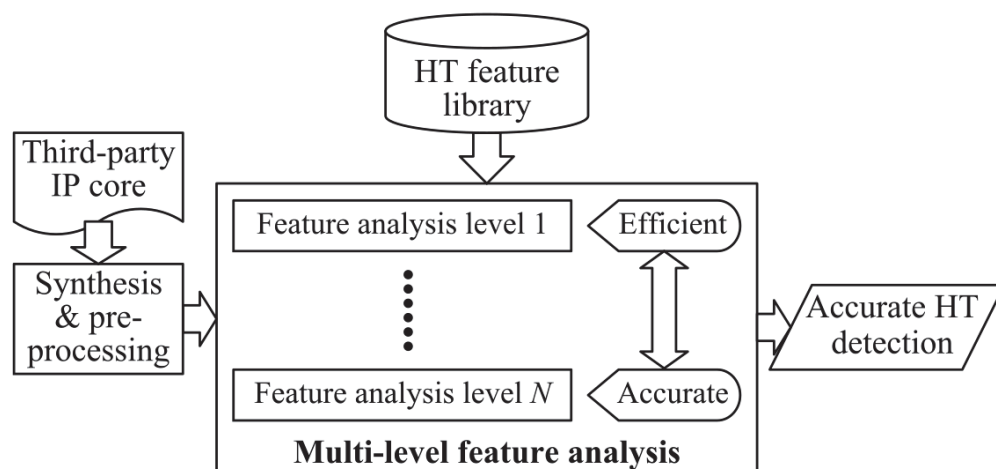
# Countermeasures against Attacks on Hardware Itself

- **IP protection:** logic encryption/locking, camouflaging, split manufacturing

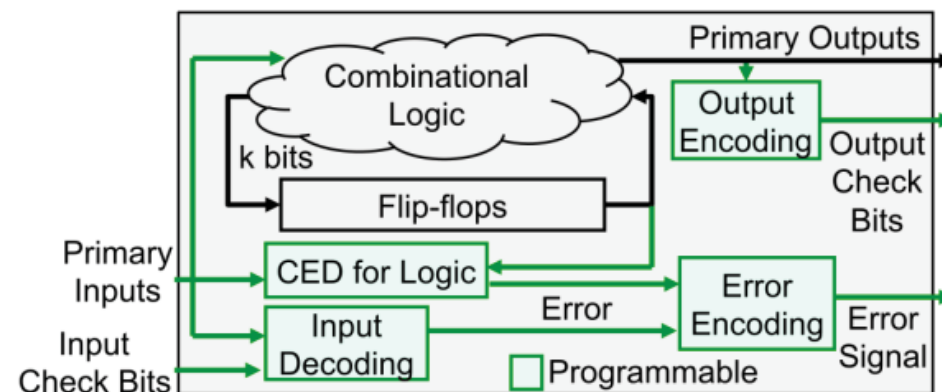


## Countermeasures against Attacks on Hardware Itself

- **IP protection:** logic encryption/locking, camouflaging, split manufacturing
- **Trojan defense:** detection, mitigation



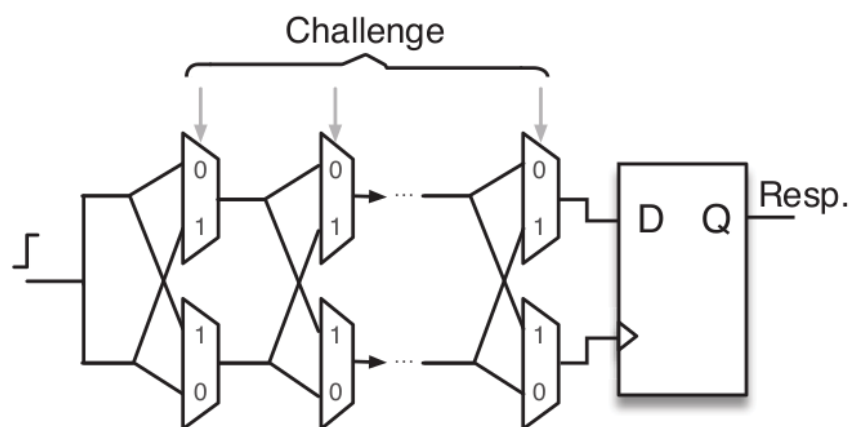
Chen et al., TCAD 2018



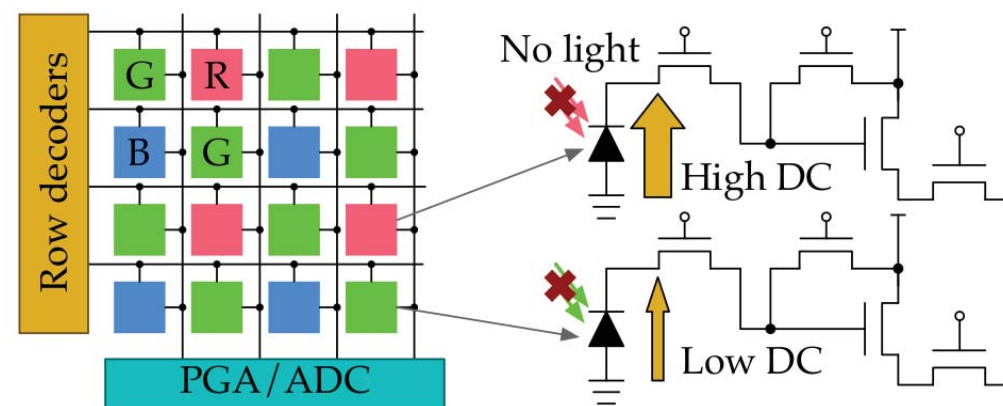
Wu et al., TCAD 2016

## Countermeasures against Attacks on Hardware Itself

- **IP protection:** logic encryption/locking, camouflaging, split manufacturing
- **Trojan defense:** detection, mitigation
- **Physically-unclonable functions (PUFs):** fingerprinting, challenge-response authentication



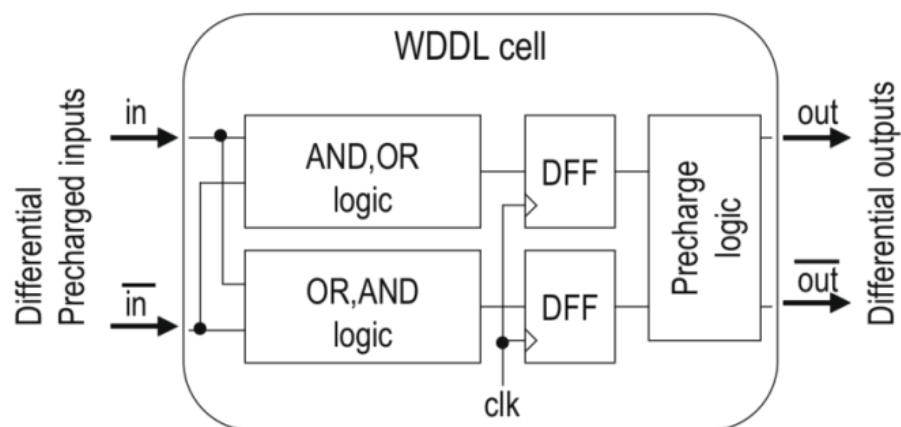
Vatajelu19, IOLTS, 2019



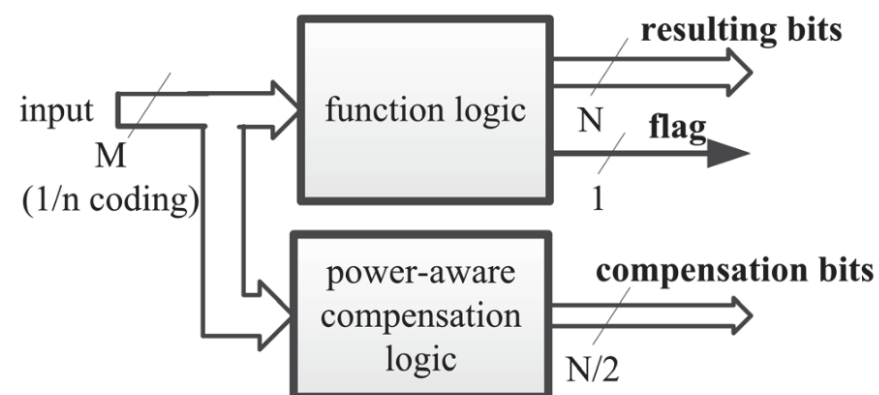
Kim and Lee, DAC, 2018

## Countermeasures against Attacks on Data and Computation

- **Masking** against side-channel and fault-injection attacks



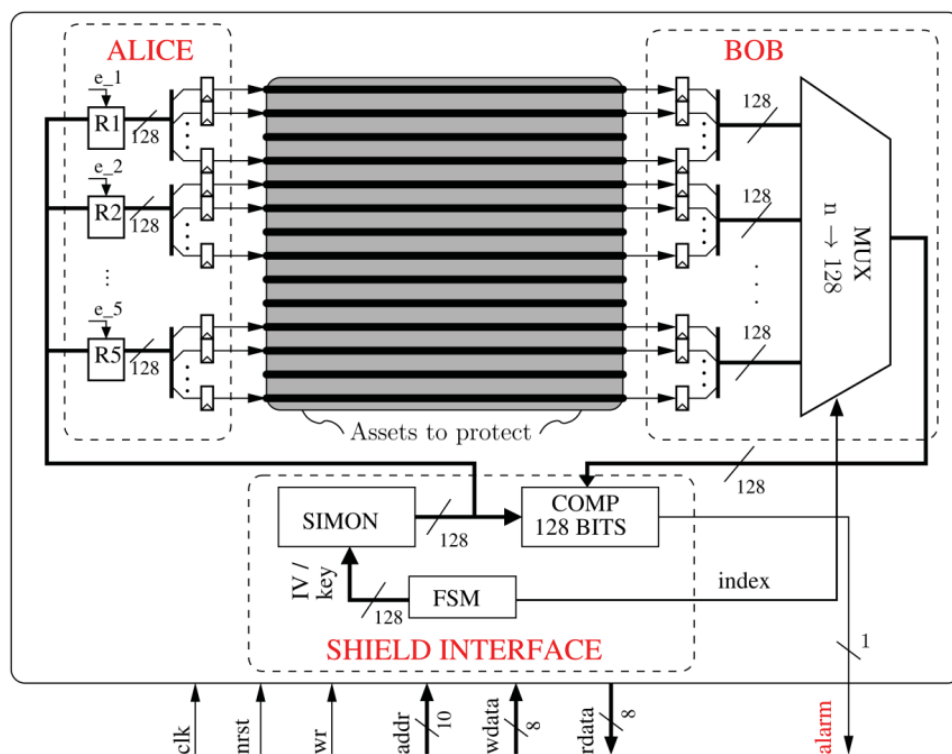
Fujimoto et al., EMC 2014



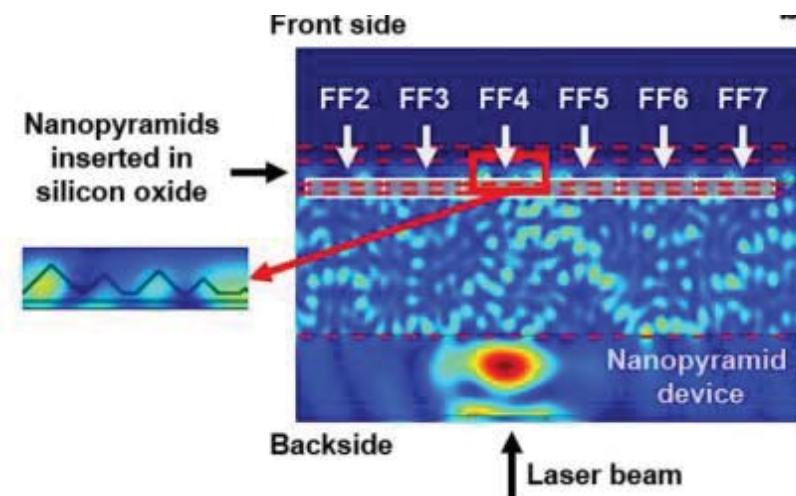
Li et al., TVLSI 2017

## Countermeasures against Attacks on Data and Computation

- **Masking** against side-channel and fault-injection attacks
- **Shielding** against probing (front side, back side)

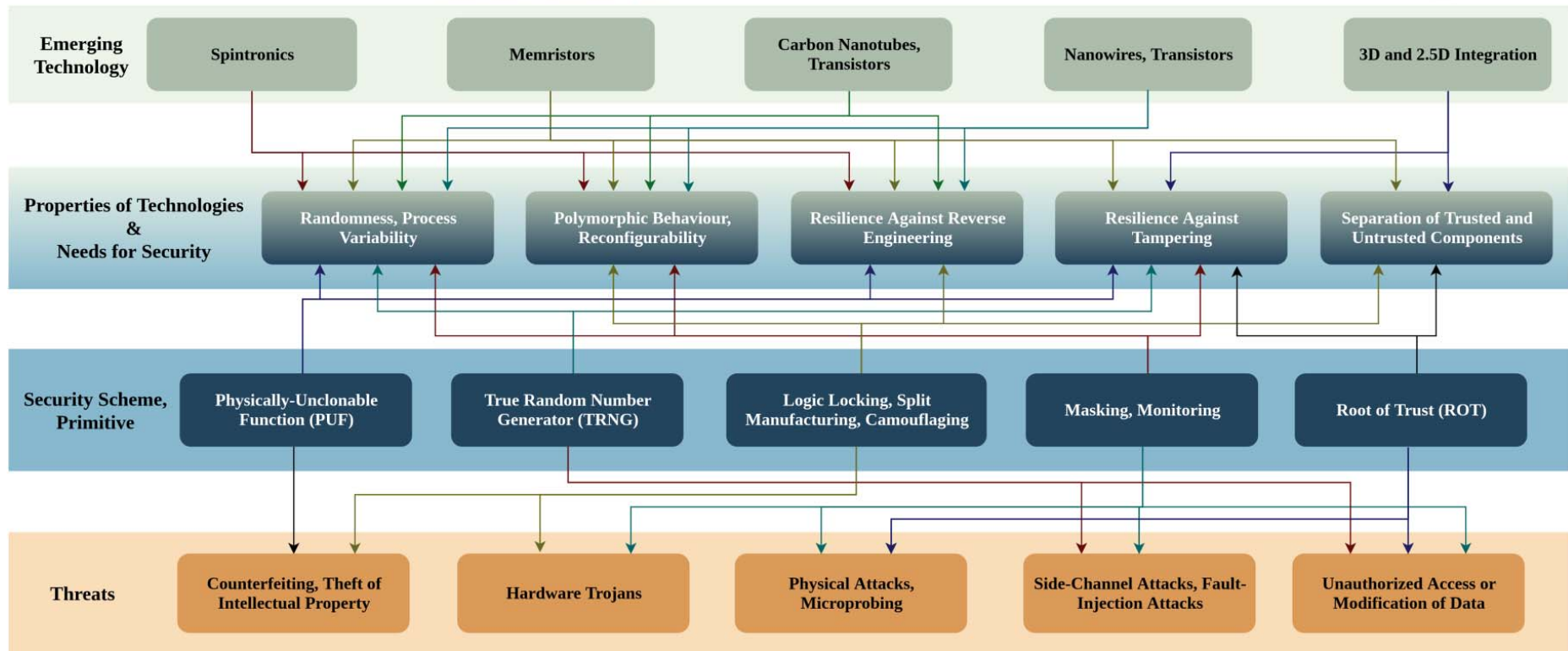
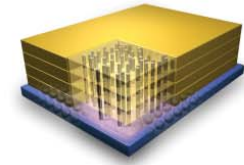
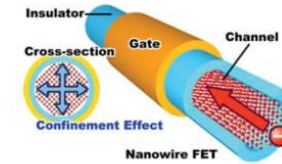
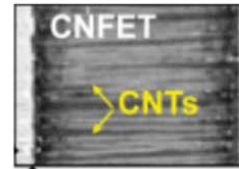
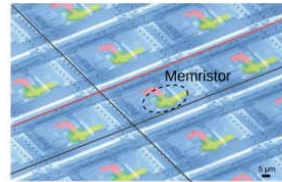
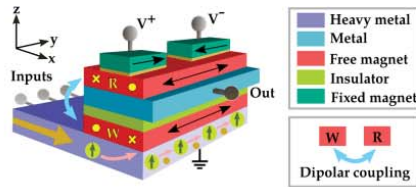


Ngo et al.,  
TC 2017

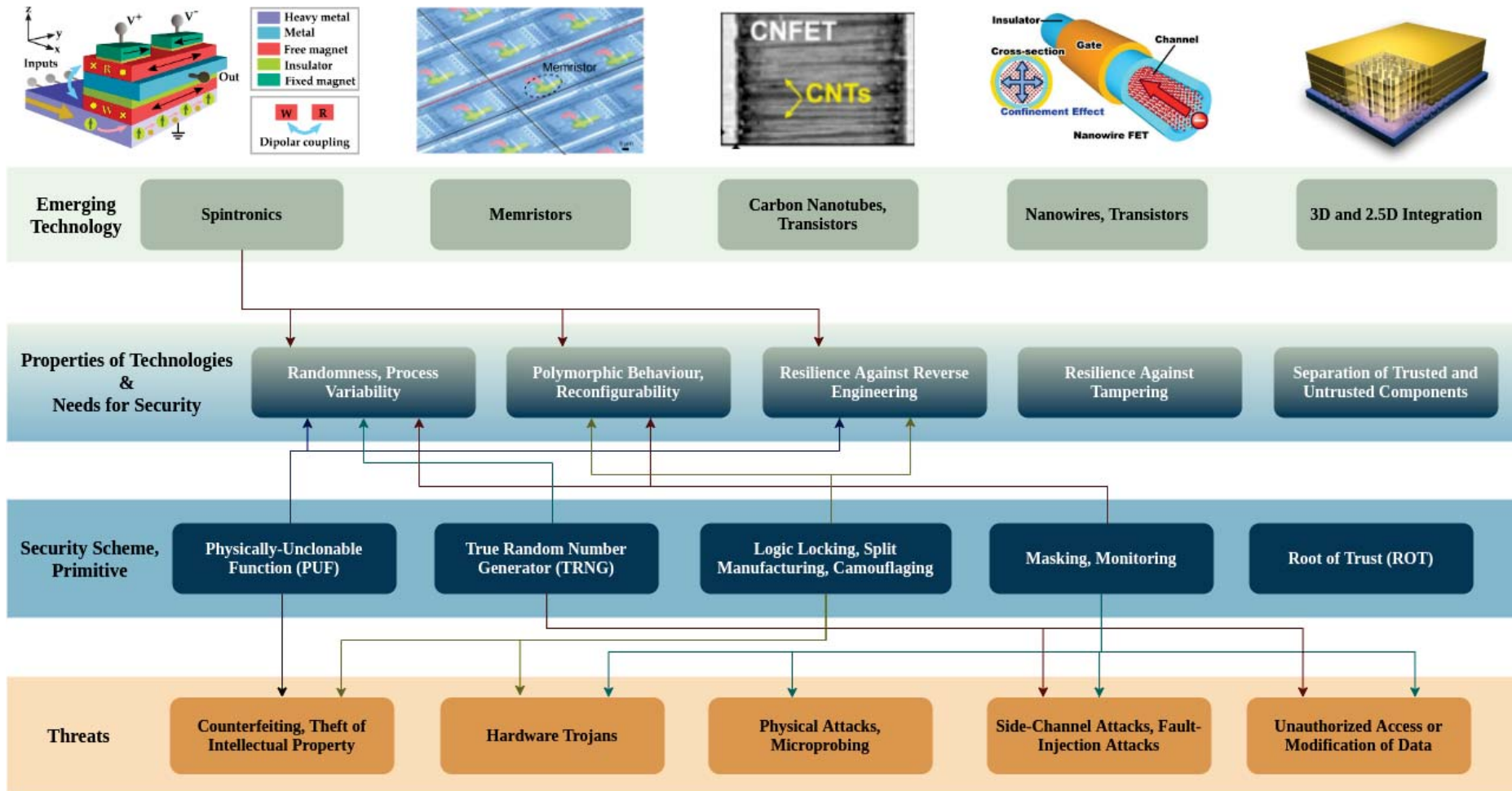


Shen et al., ISTFA 2018

# Emerging Technologies for Hardware Security

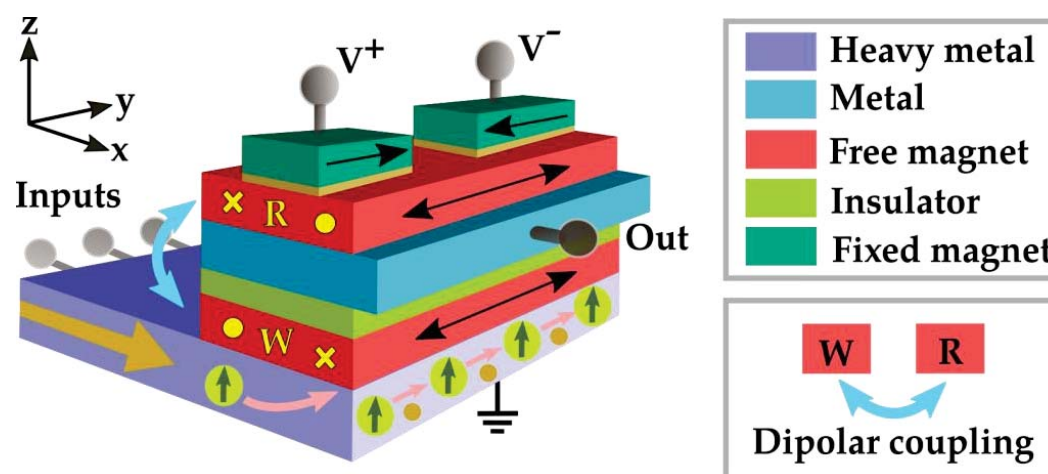


# Emerging Technologies for Hardware Security: Spintronics



## Basics of Spintronics

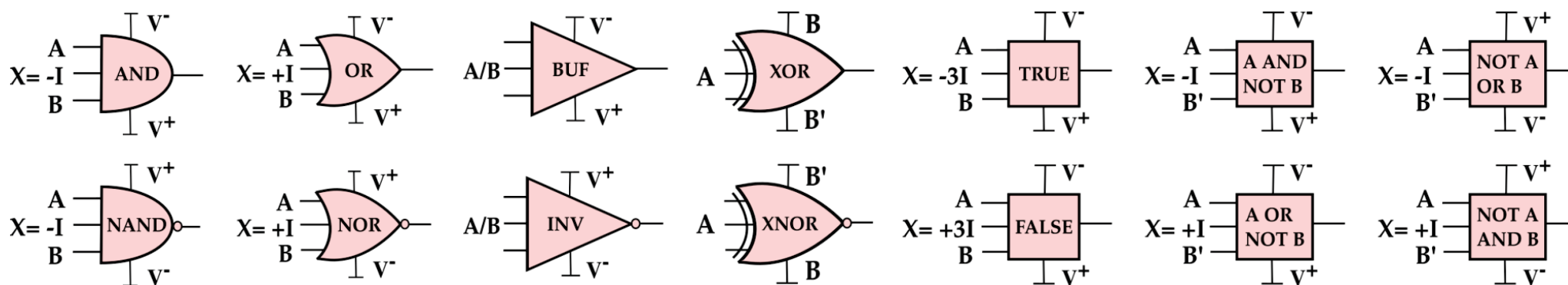
- Besides electronic charge, *spin* of electrons is leveraged for computation and memory
- Switching process is non-volatile, magnetoelectric, and subject to phenomena like spin-transfer torque (STT)
- Typically implemented in BEOL as stack of heavy metals, ferromagnets, and oxide structures; compatible with CMOS



Patnaik et al., TCAD 2019

## Basics of Spintronics

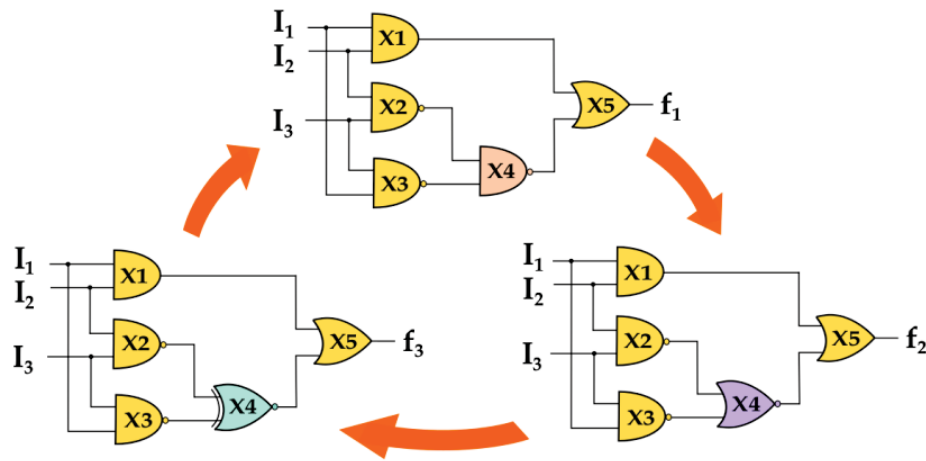
- Compared to CMOS, spintronics can offer lower power consumption, built-in memory functionality, built-in reconfigurability, and better scalability
- Notable efforts by Intel, UC Berkeley, and Berkeley Lab
- Reconfigurable logic, probabilistic computing, and in-memory computing



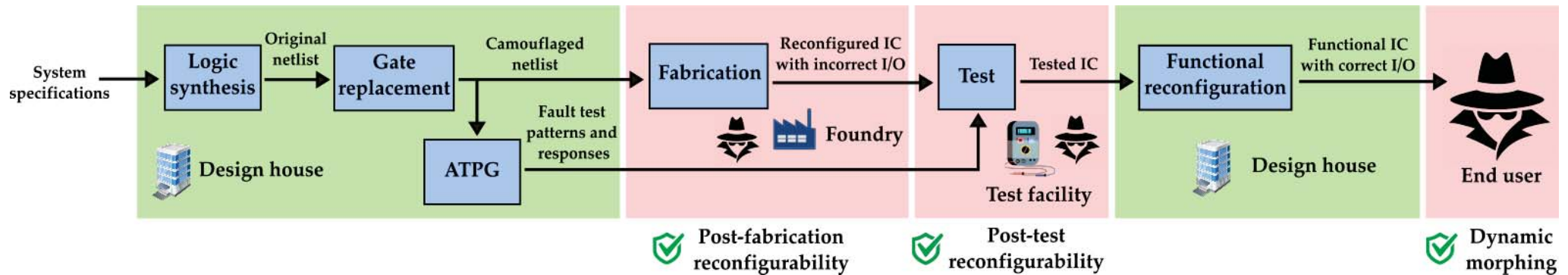
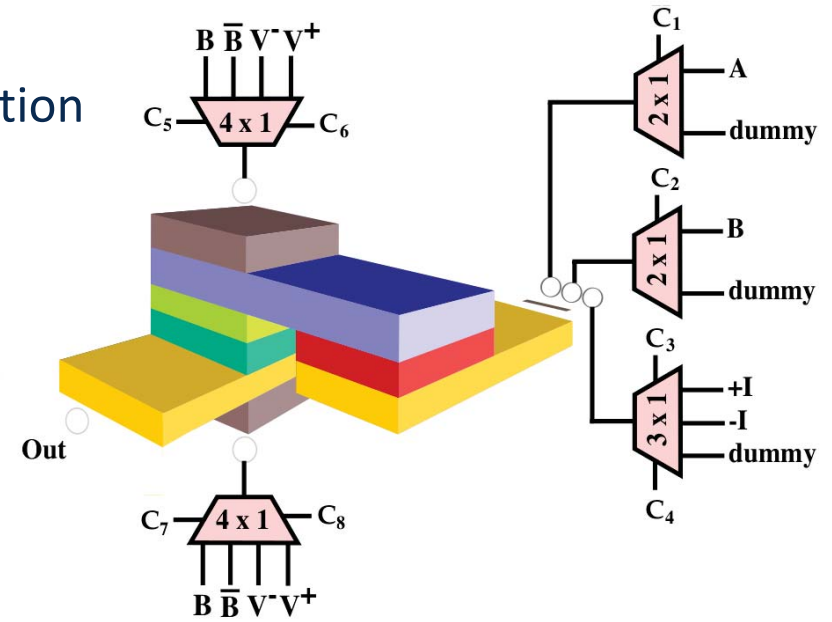
Patnaik et al., TCAD 2019

# Spintronics for Hardware Security

- **Dynamic camouflaging** as novel paradigm for IP protection

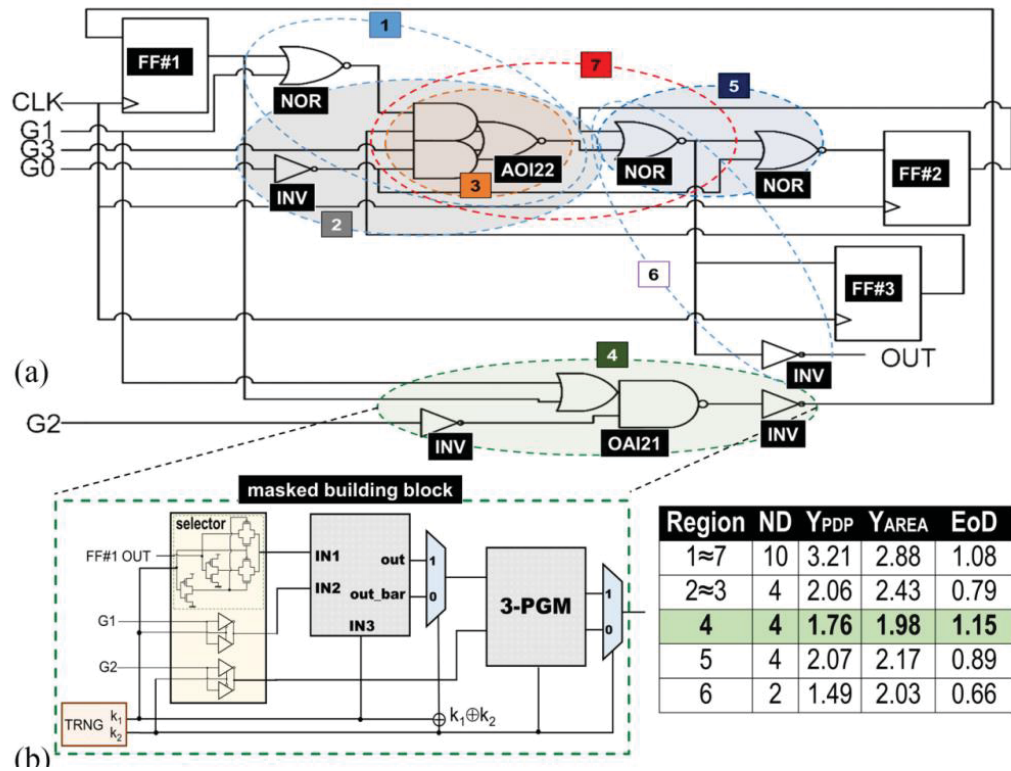


Rangarajan et al.,  
TETC, 2020

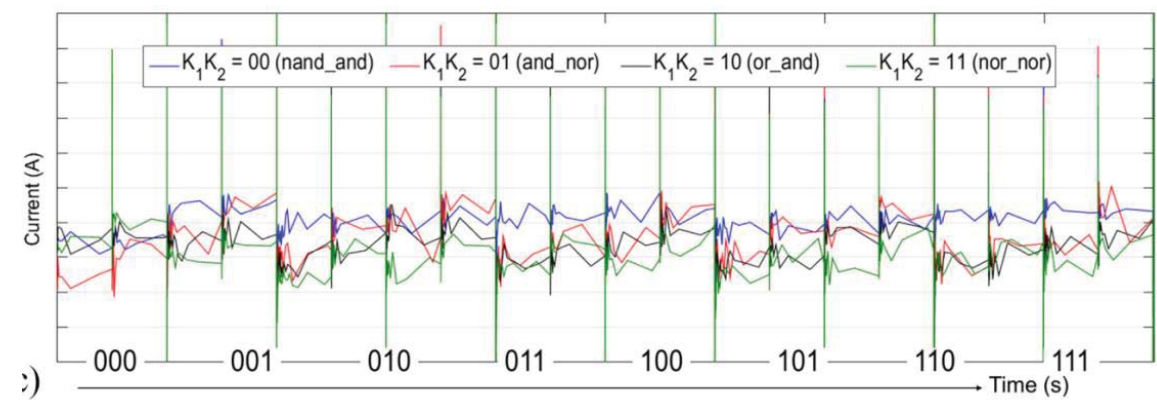


# Spintronics for Hardware Security

- **Dynamic camouflaging** as novel paradigm for IP protection
- **Polymorphic, non-CMOS switching** to mitigate side-channel leakage



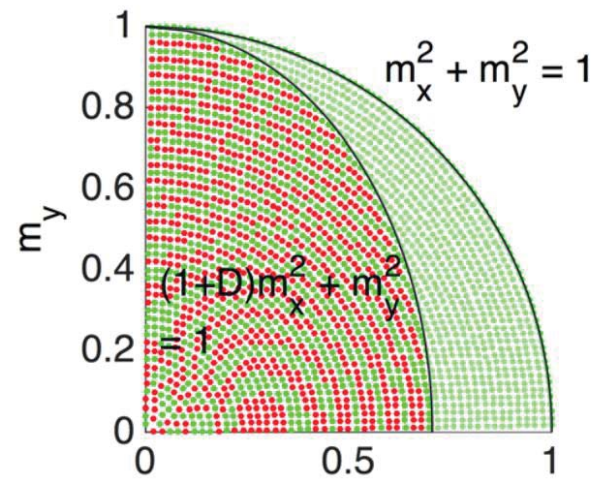
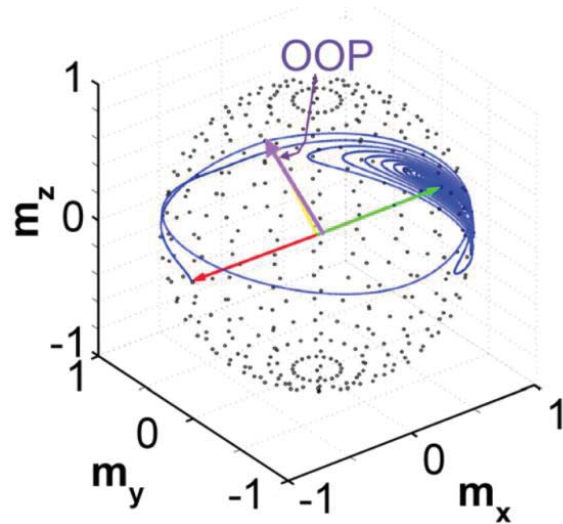
Region	ND	Y <sub>DPD</sub>	Y <sub>AREA</sub>	EoD
1≈7	10	3.21	2.88	1.08
2≈3	4	2.06	2.43	0.79
4	4	1.76	1.98	1.15
5	4	2.07	2.17	0.89
6	2	1.49	2.03	0.66



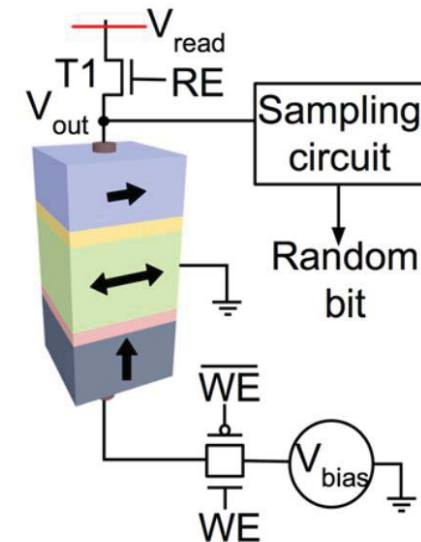
Roohi et al.,  
TNANO, 2019

## Spintronics for Hardware Security

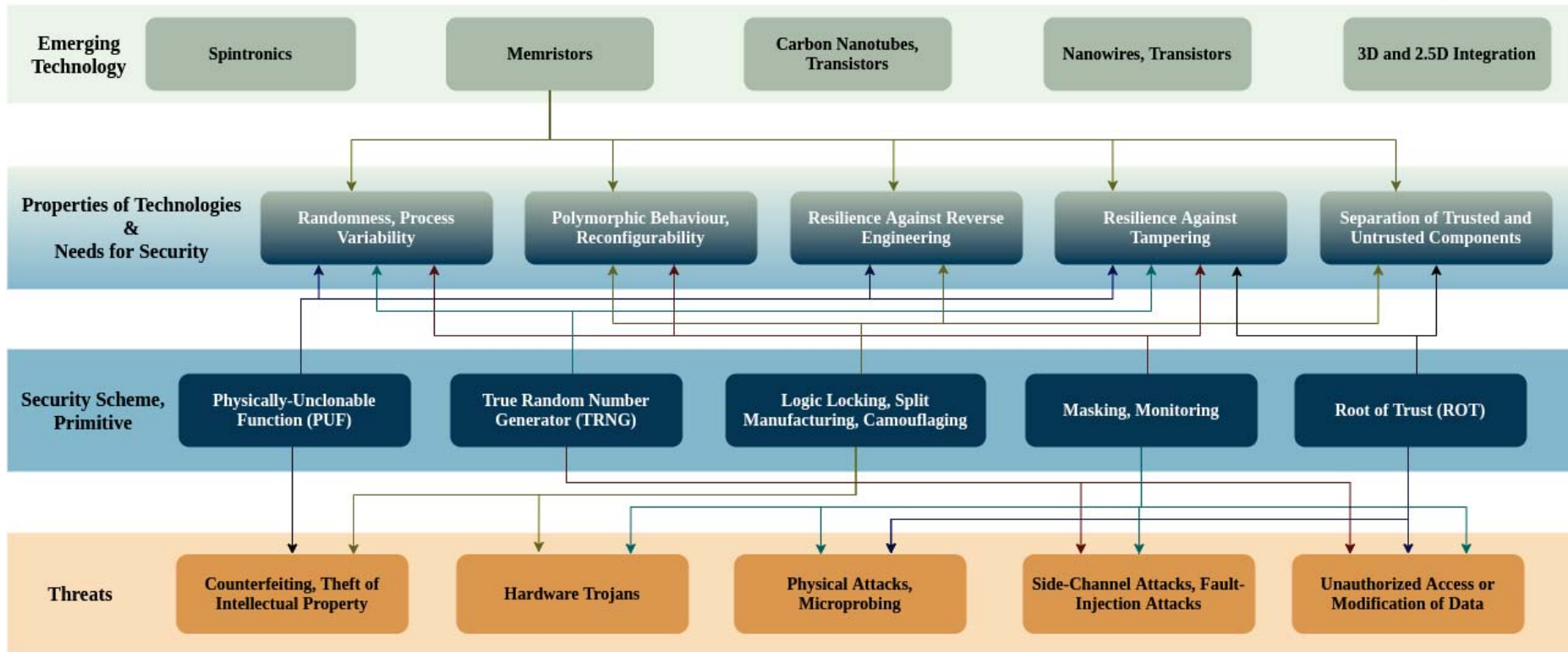
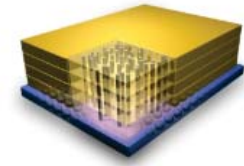
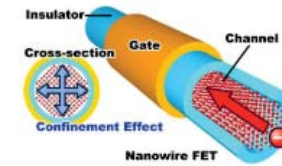
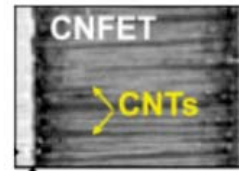
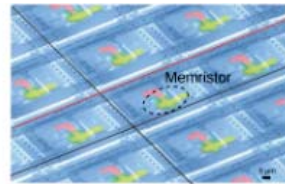
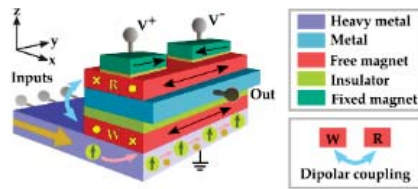
- **Dynamic camouflaging** as novel paradigm for IP protection
- **Polymorphic, non-CMOS switching** to mitigate side-channel leakage
- **Tunable switching processes** for PUFs and TRNGs



Rangarajan et al., JAP, 2017

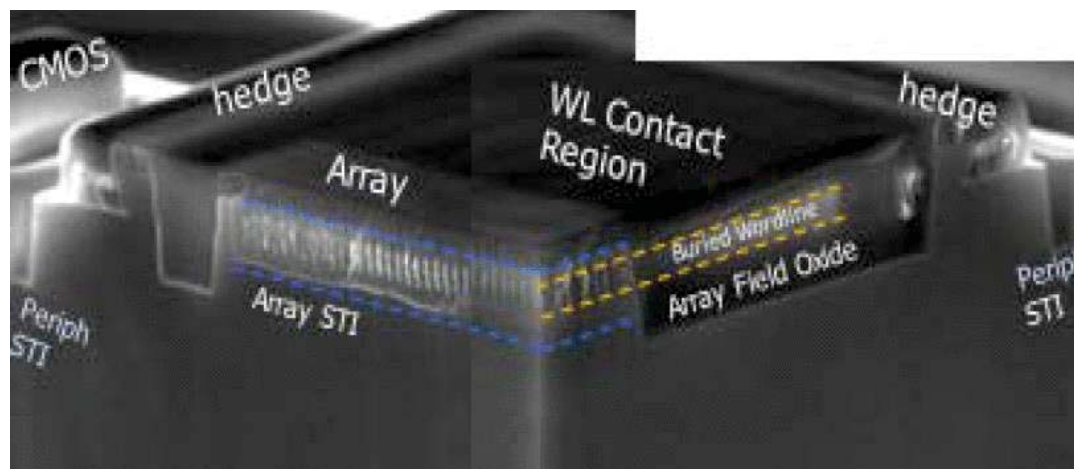
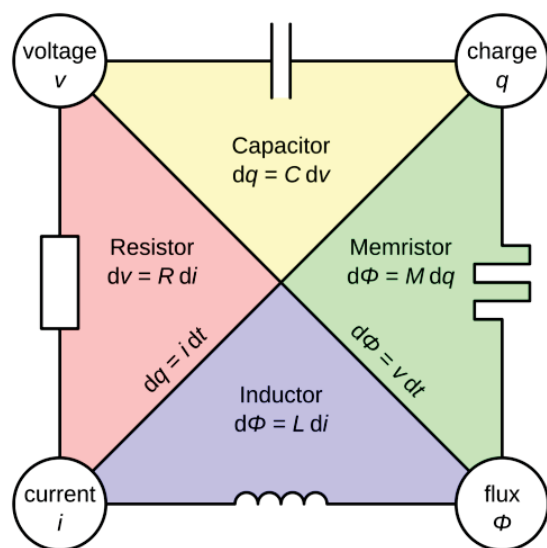


# Memristors for Hardware Security



## Basics of Memristors

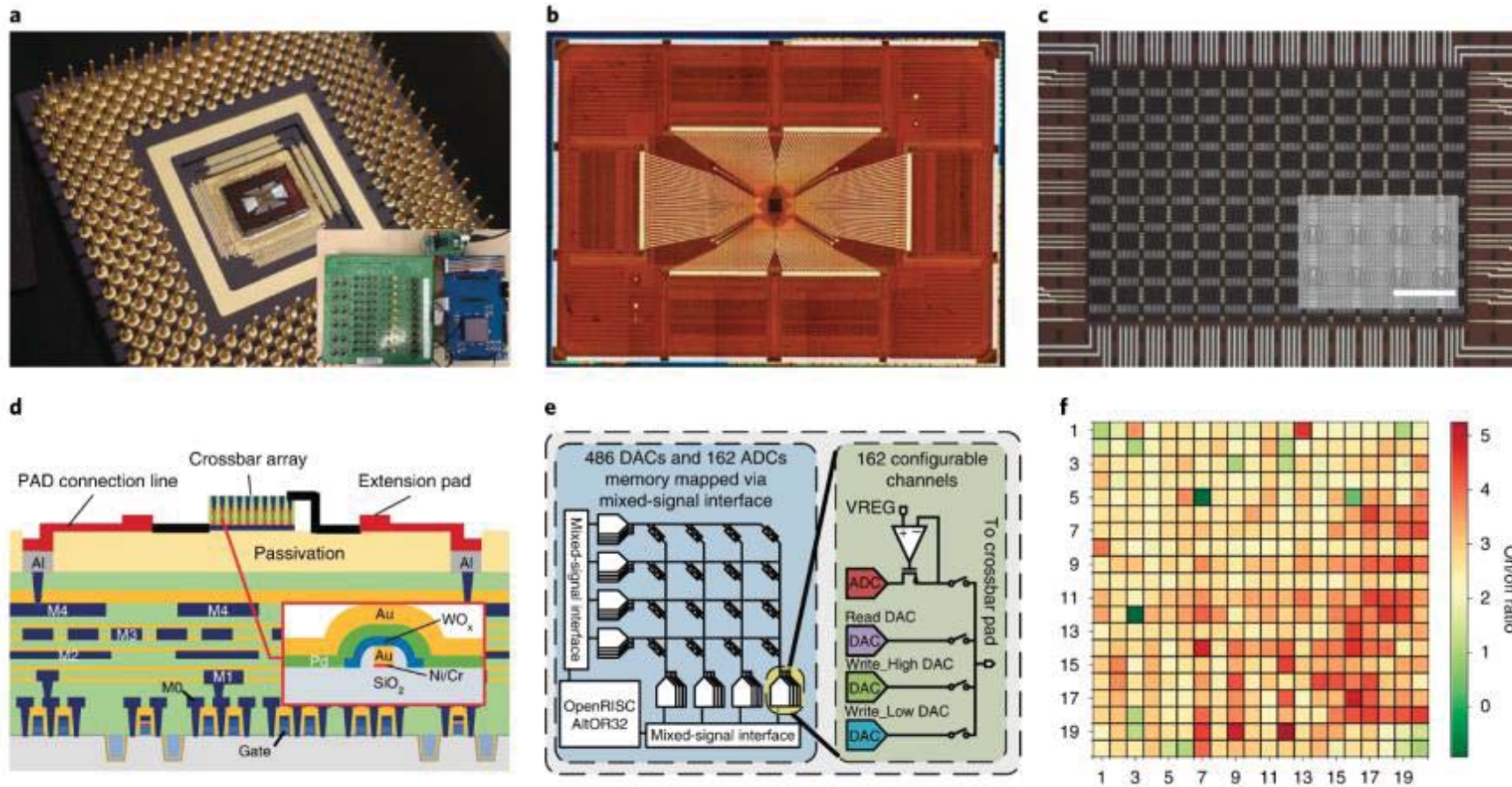
- Memory resistor, another fundamental circuit element
- Retain an internal resistive state according to the history of voltage or current applied
- For some, nonlinear response (pinched hysteresis loops)
- R&D considering various materials and arrangements like titanium dioxide – can be made compatible with CMOS



Zahurak et al., IEDM 2014

# Basics of Memristors

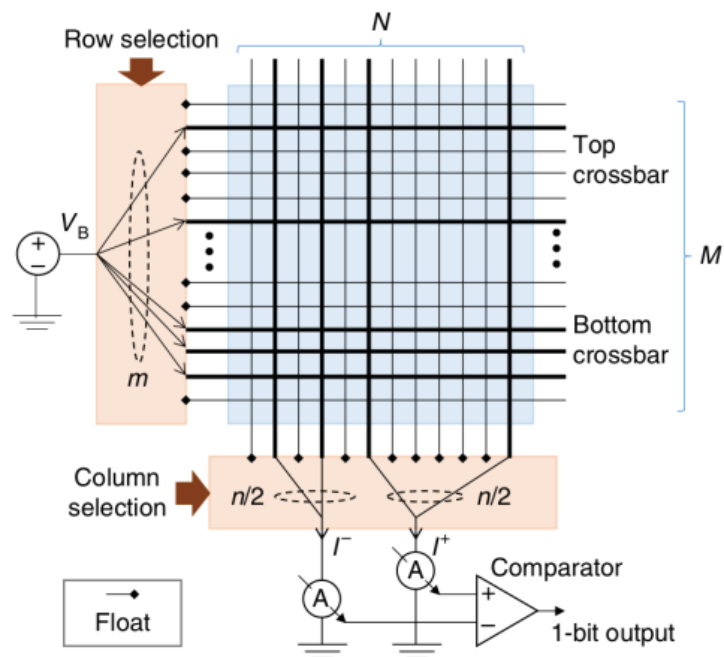
- In-memory computing, neuromorphic computing, and reconfigurable logic



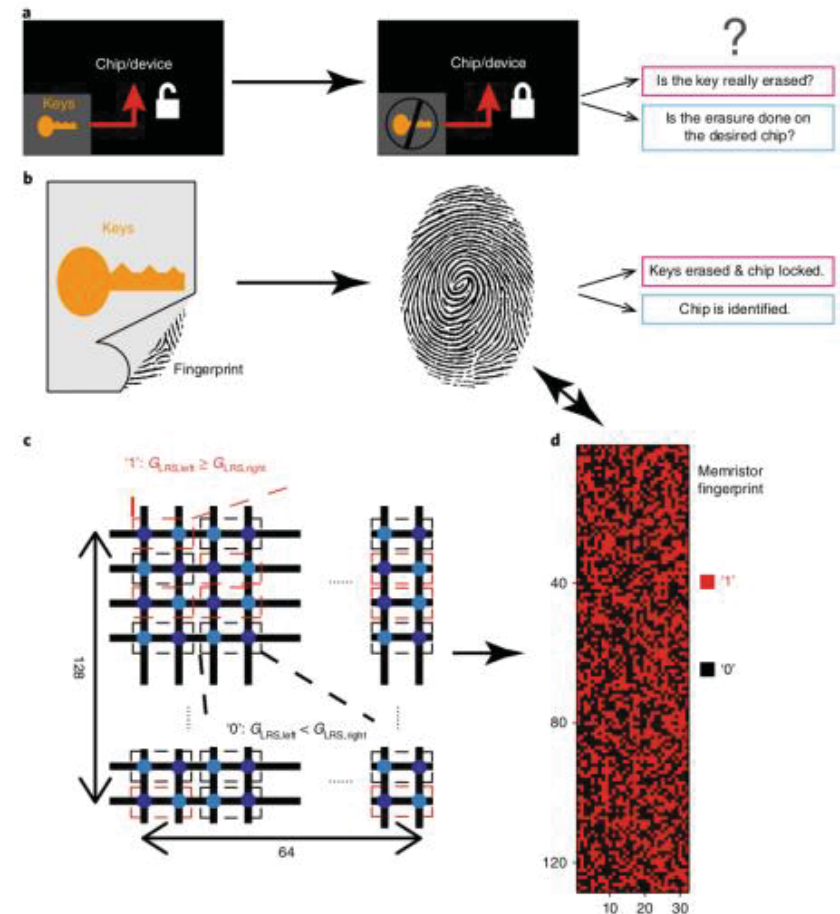
Cai et al.,  
Nature 2019

# Memristors for Hardware Security

- Nonlinear variations for PUFs
- Secure key management, e.g., for locking
- IP protection via by polymorphic behavior and separation of components

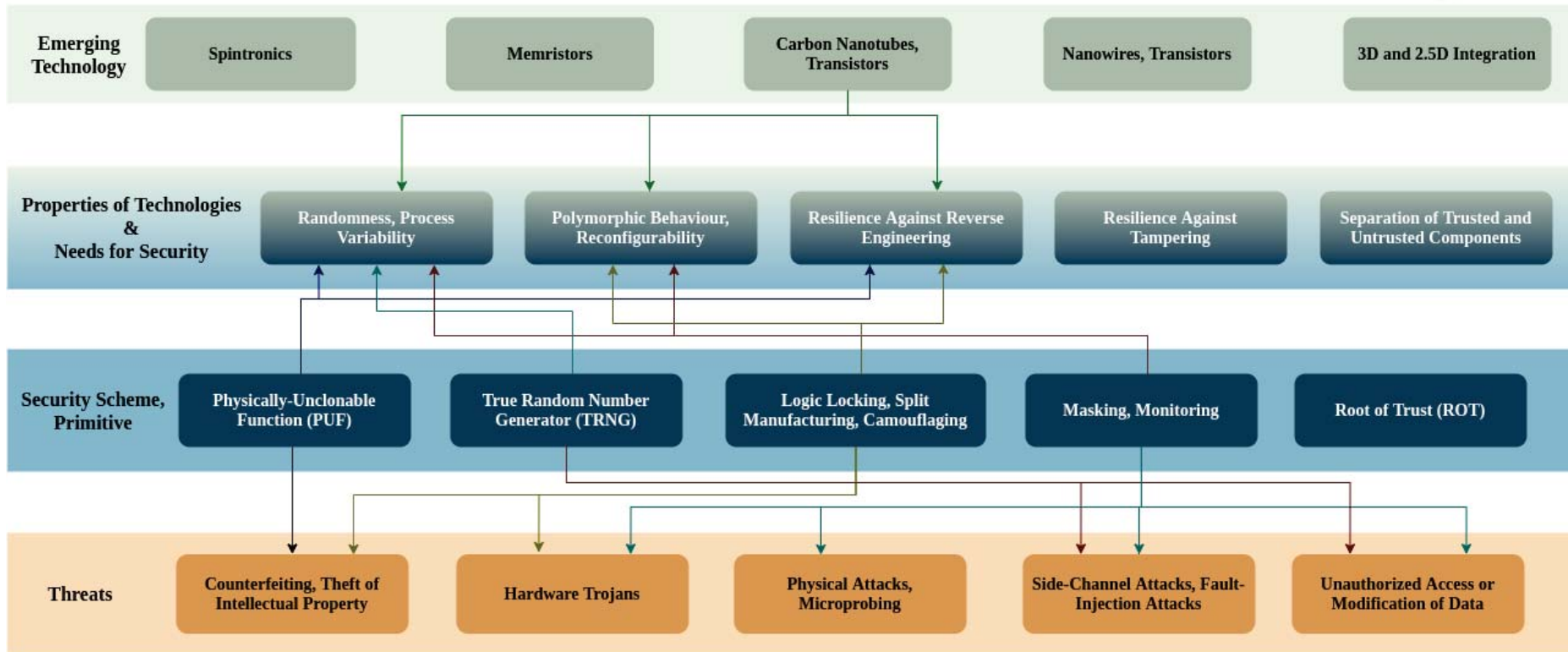
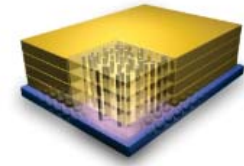
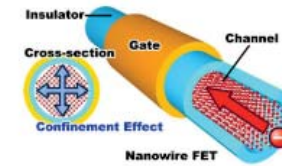
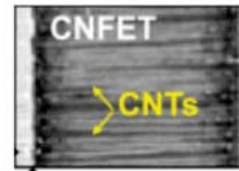
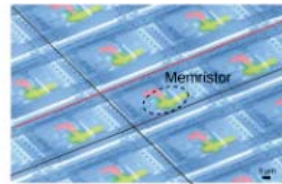
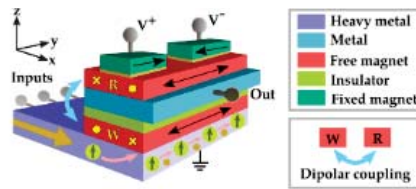


Nili et al.,  
Nature 2018



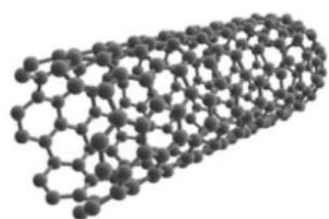
Jiang et al., Nature 2018

# Carbon Nanotubes for Hardware Security

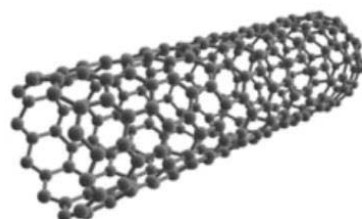


## Basics of Carbon Nanotube Transistors

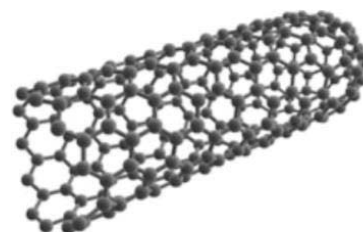
- Carbon nanotubes (CNTs): one or more rolled-up layers of graphene, the planar arrangement of single-layer carbon atoms in 2D honeycomb-like structures
- Either metallic conductors or semiconductors, depending on structure
- Outstanding electrical, physical, and thermal properties
  - Due to the strong bonds between C atoms
  - Individual metallic CNTs can hold current densities more than 1,000 times greater than copper
- Used for interconnects and transistors



(a) Armchair

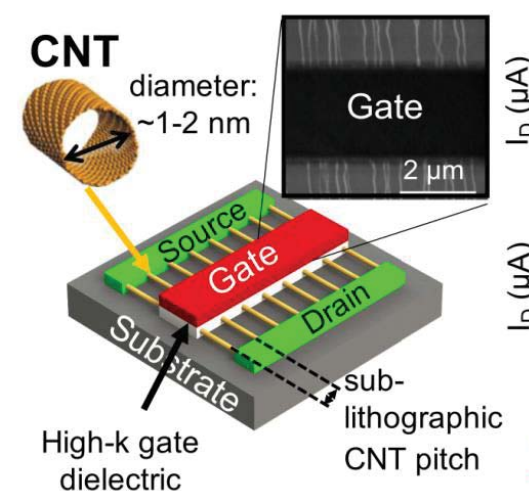


(b) Zig-zag



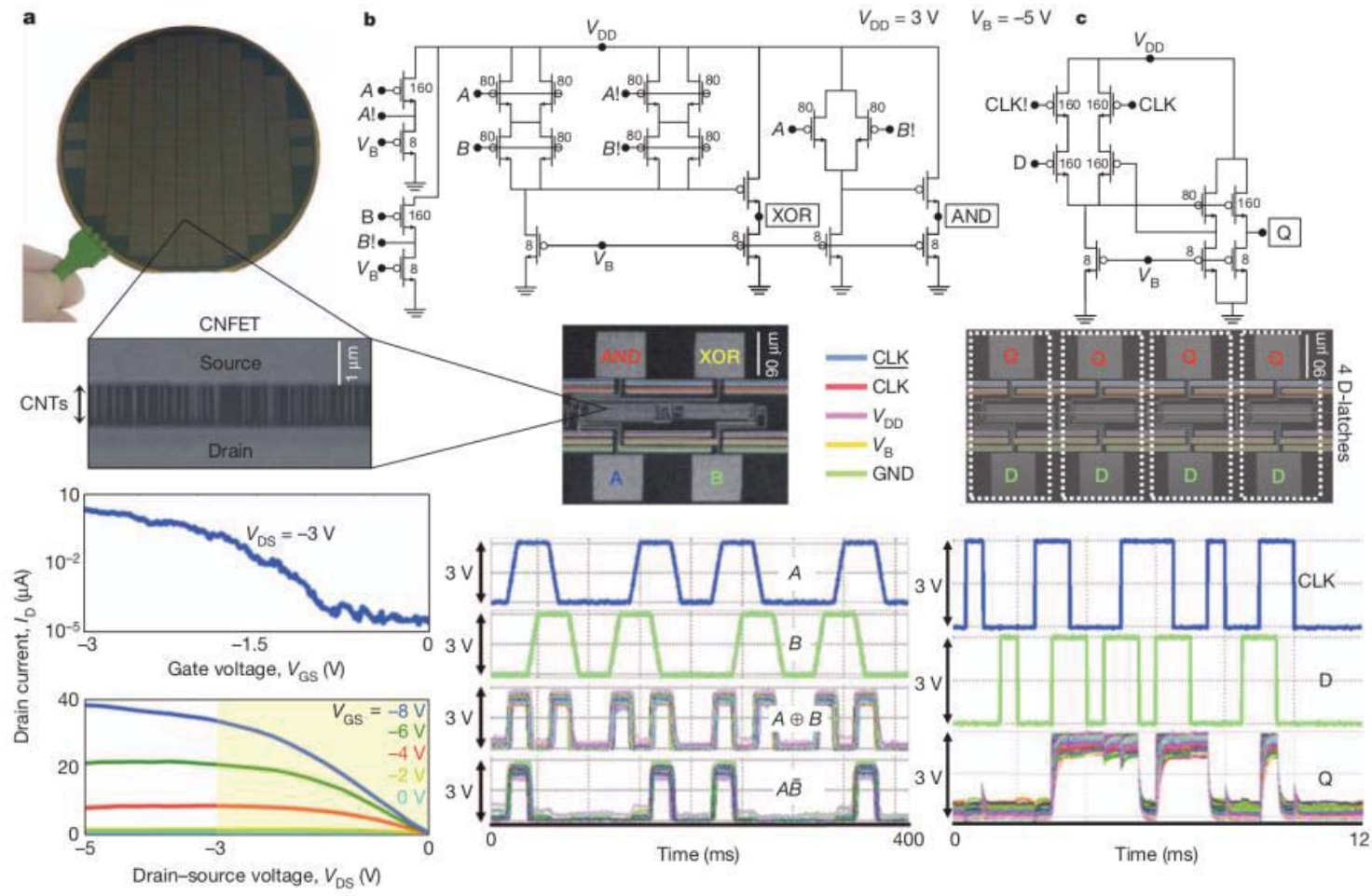
(c) Chiral

Lienig and Thiele, Springer, 2018



Wu et al.,  
JSSC 2018

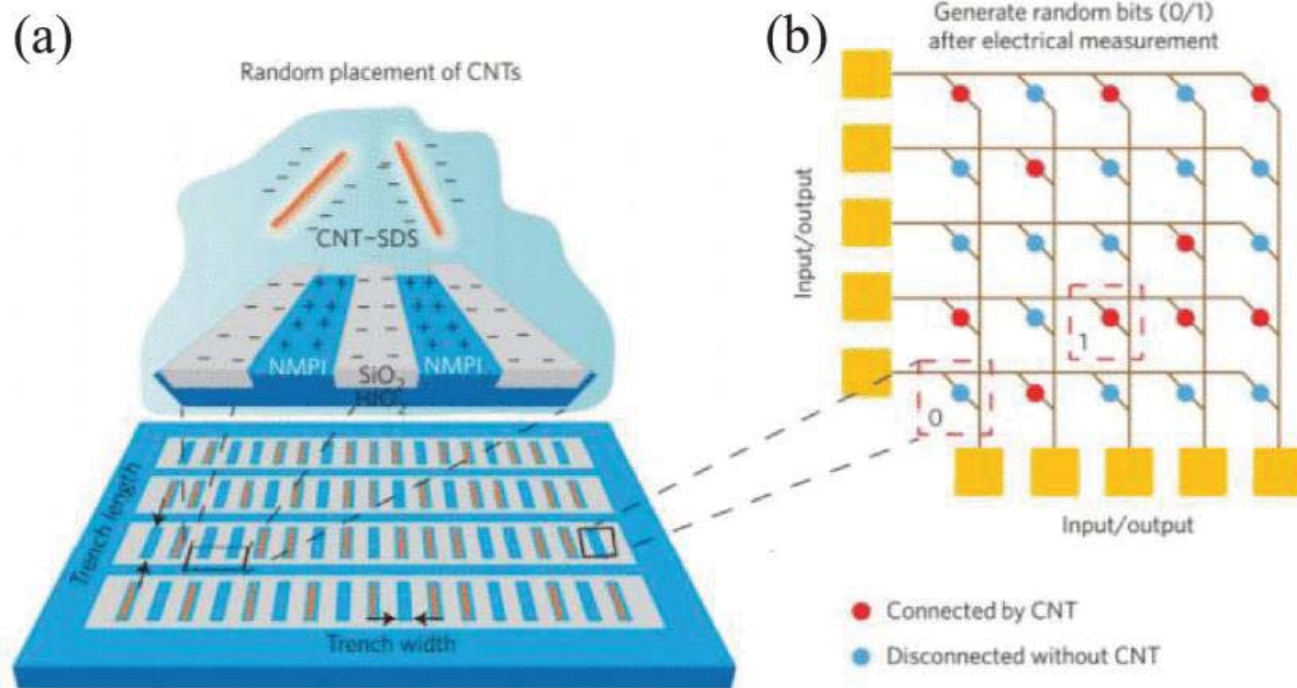
# Basics of Carbon Nanotube Transistors



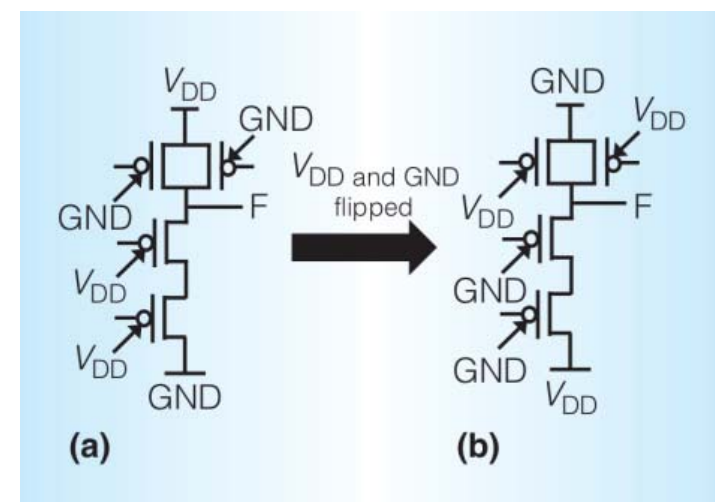
Shulaker et al.,  
Nature 2013

## Carbon Nanotubes for Hardware Security

- Manufacturing variability for PUFs and TRNGs
- IP protection by reconfigurability

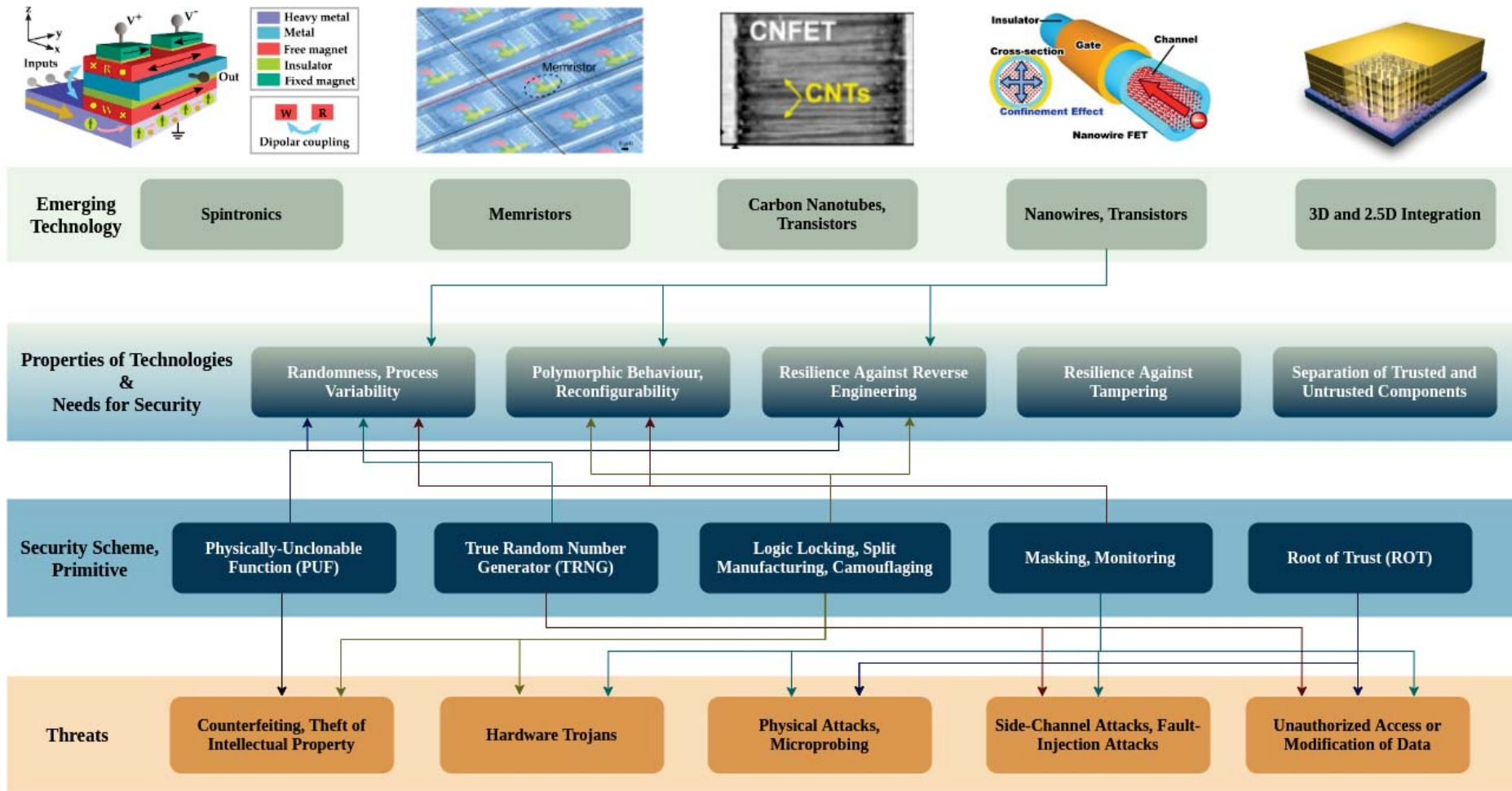


Rahman et al., TVLSI, 2017



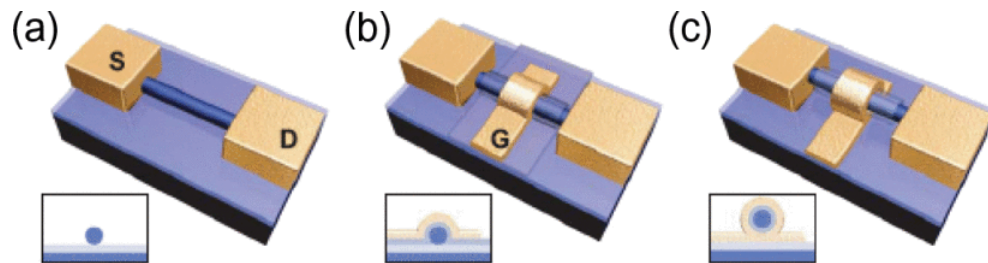
Suresh et al., Micro, 2016

# Emerging Technologies for Hardware Security: Nanowire Transistors

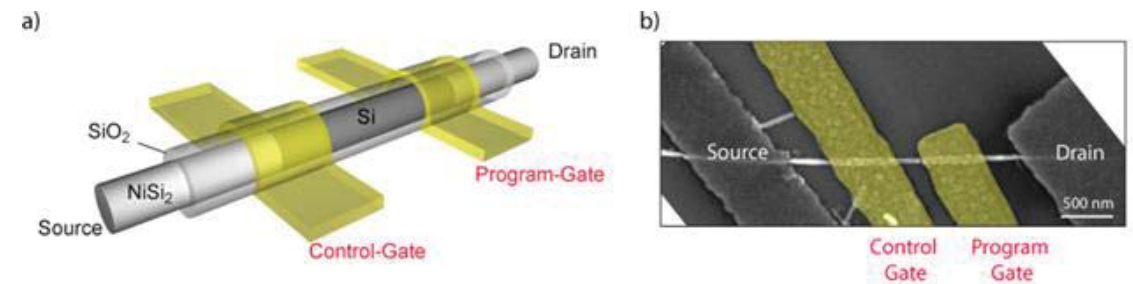


## Basics of Nanowire Transistors

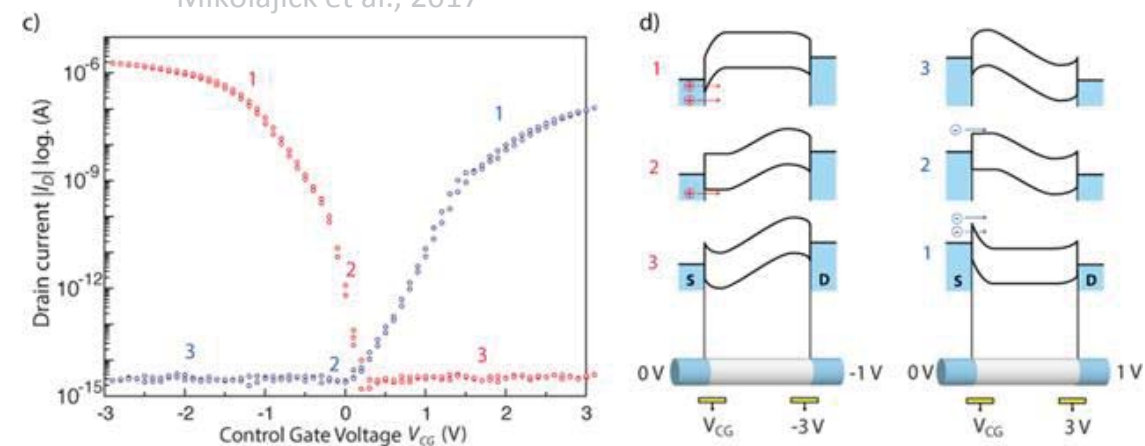
- Nano-scaled and semiconductive wires as transistor channel
- Somewhat similar to CNT-FETs, but allow for finer control of desired properties (whereas CNT-FETs offer better performance)
- Sensing applications, flexible electronics, and reconfigurable logic



Lu et al., TED 2008

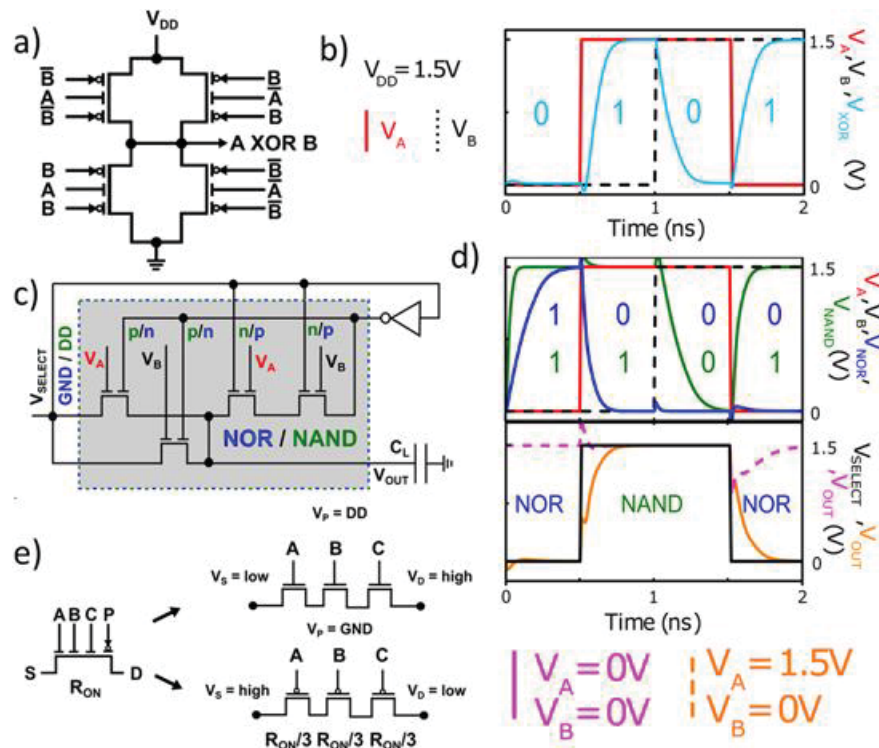


Mikolajick et al., 2017

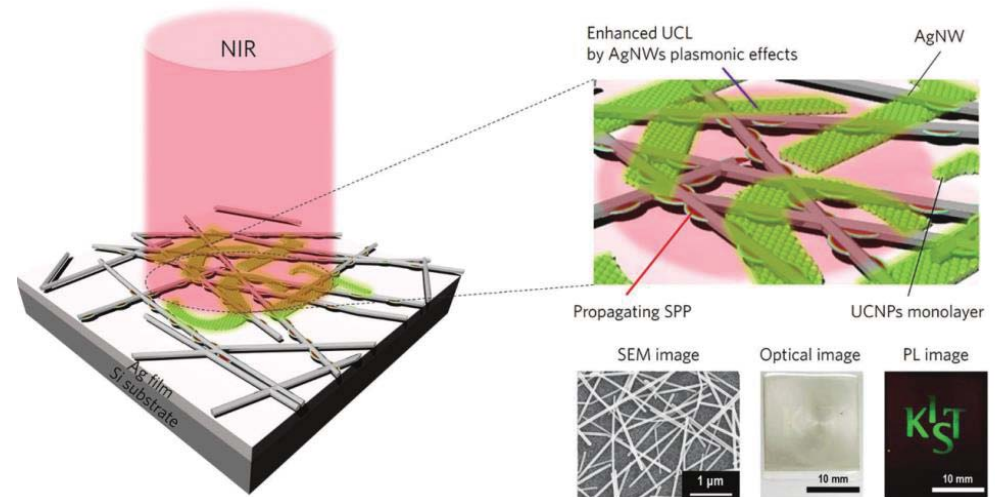


# Nanowire Transistors for Hardware Security

- Controllable ambipolarity and polymorphic behavior for IP protection
- Plasmonic interaction for tagging

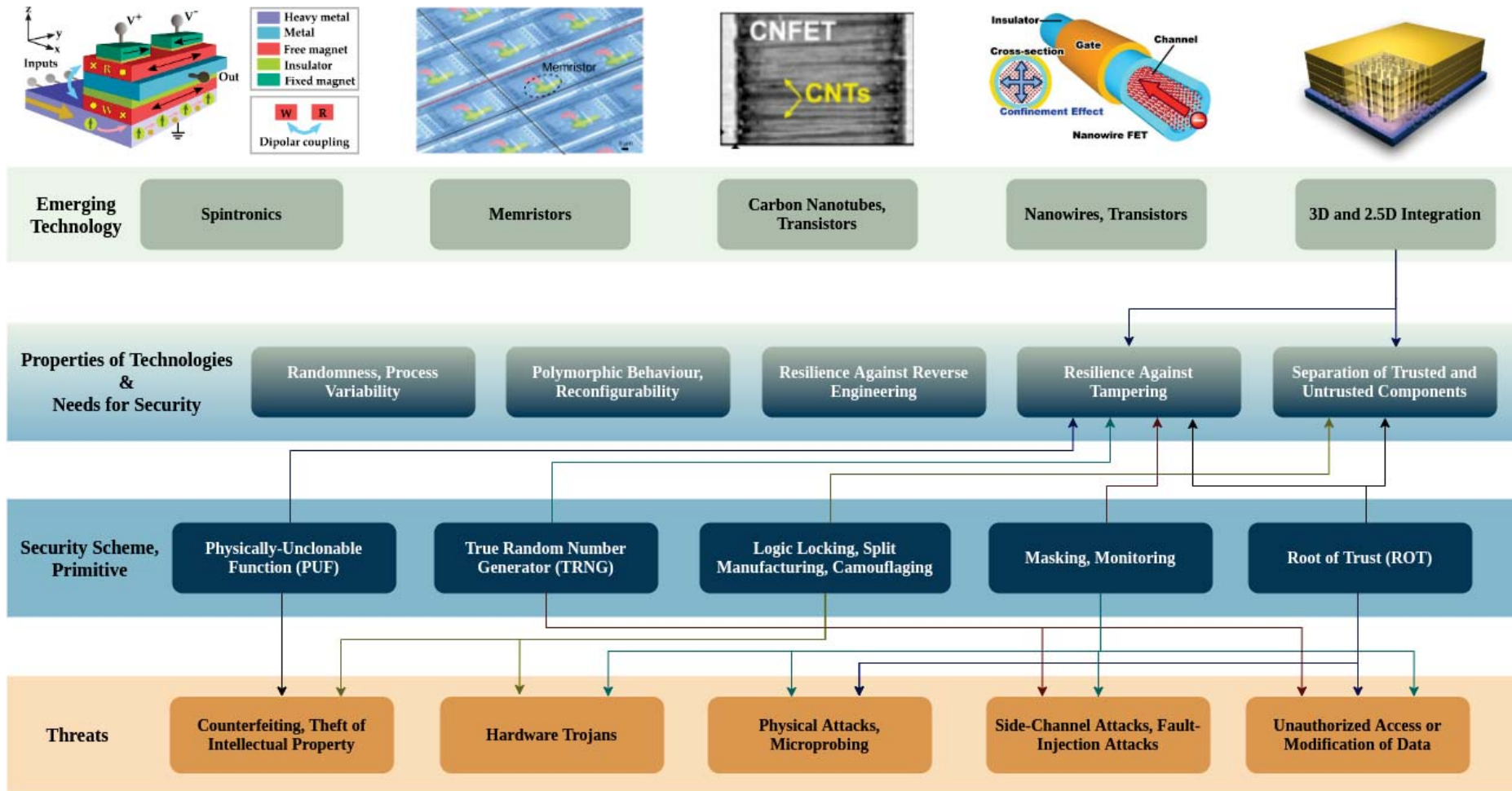


Mikolajick et al., 2017



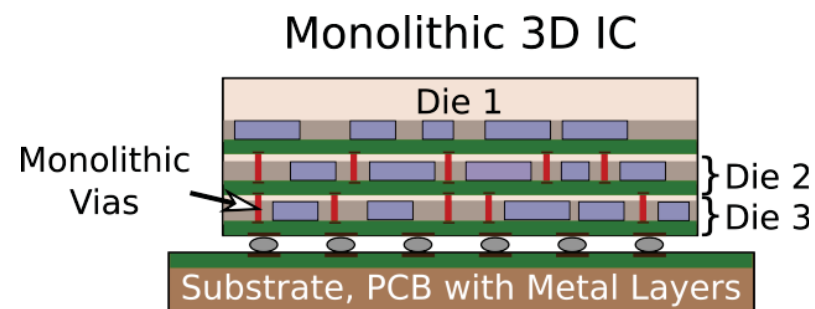
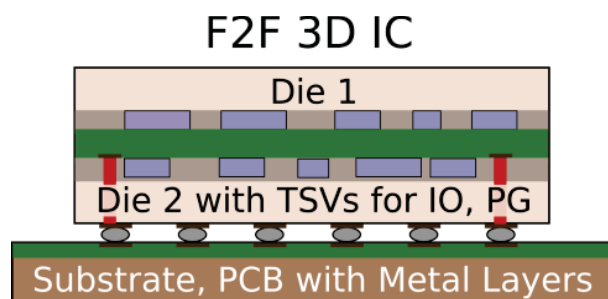
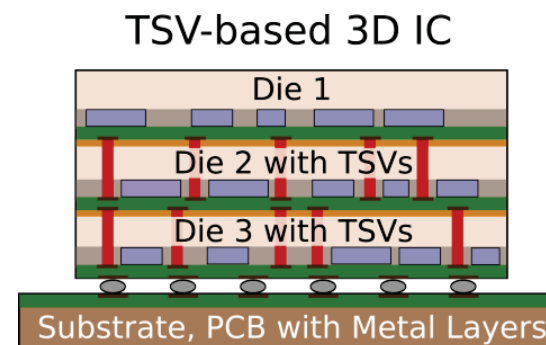
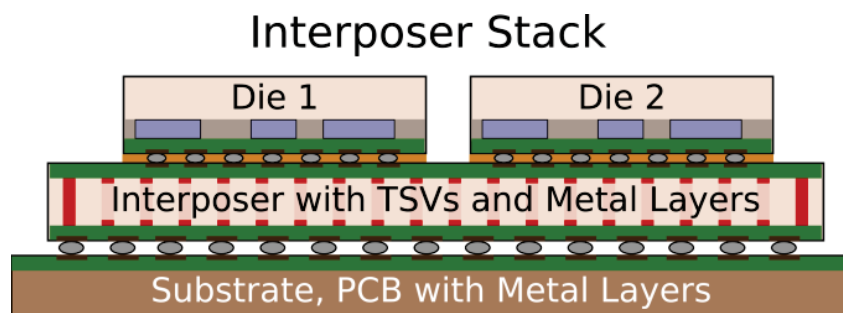
Park et al., 2016

# Emerging Technologies for Hardware Security: 2.5D and 3D Integration

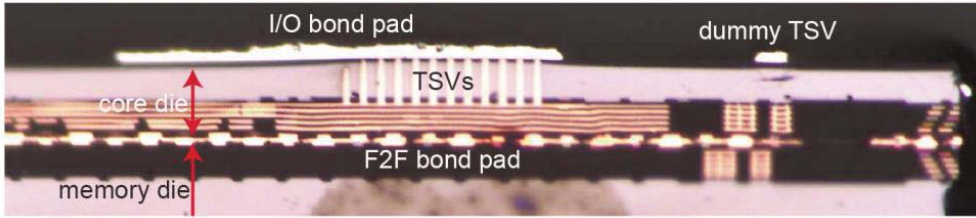


## Basics of 2.5D and 3D Integration

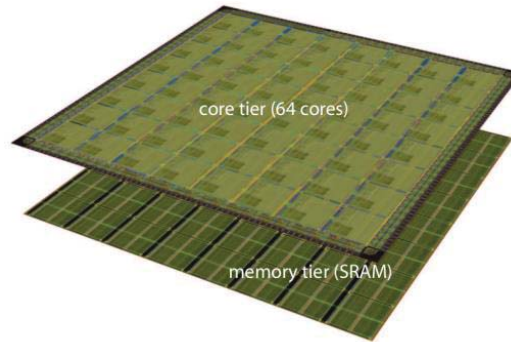
- **Shorter, vertical interconnects:** power consumption, delay, bandwidth – “More Moore”
- **Separate dies integrated:** heterogeneous, large systems; yield – “More than Moore”



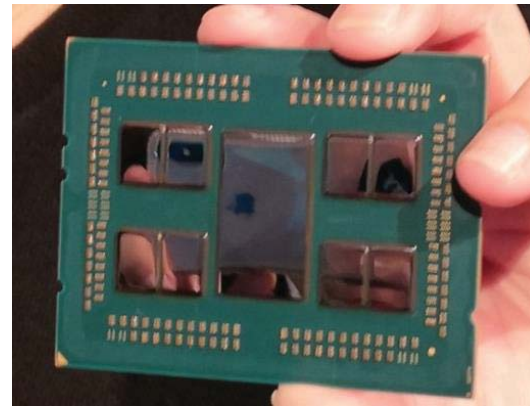
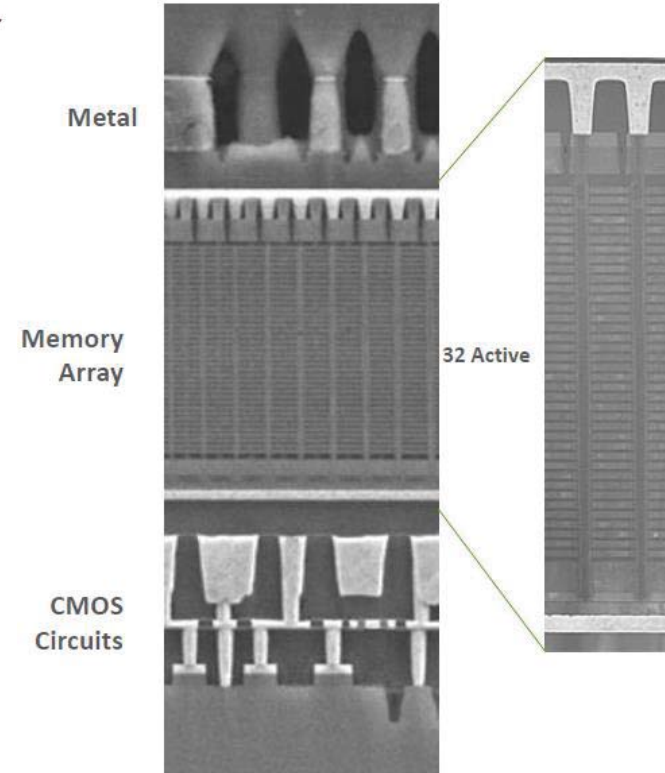
# Basics of 2.5D and 3D Integration



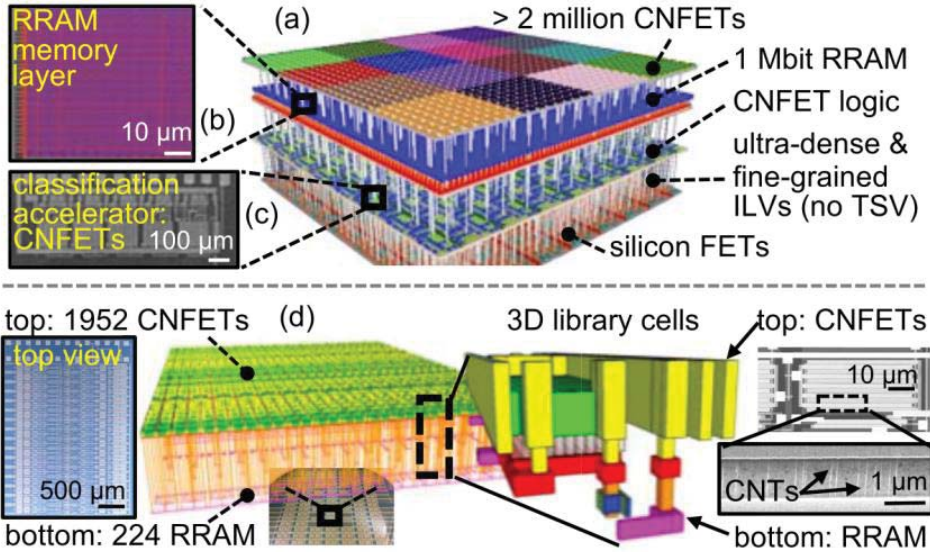
Kim et al., ISSCC, 2012



## 3D NAND Structure



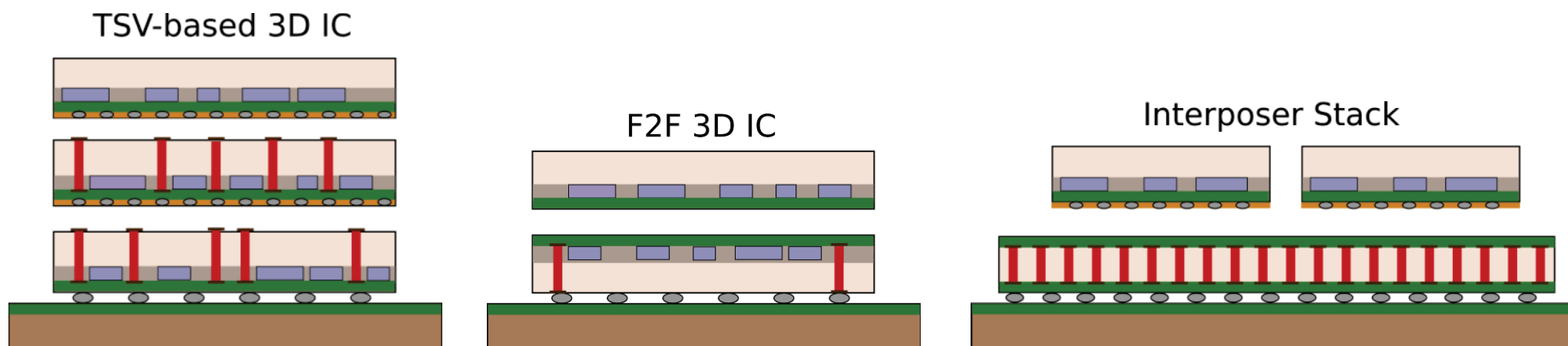
<https://www.anandtech.com>, 2016 & 2018



Aly et al., Proc. IEEE, 2019

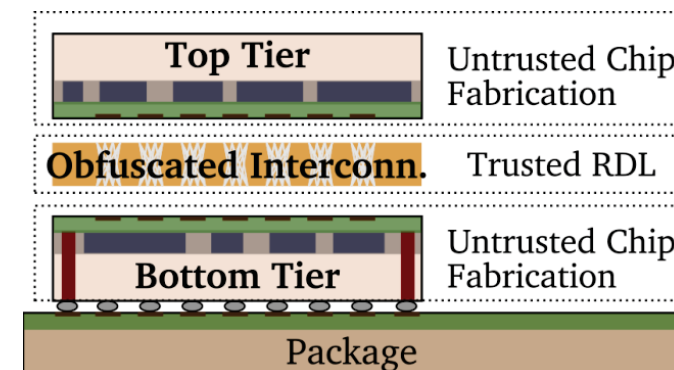
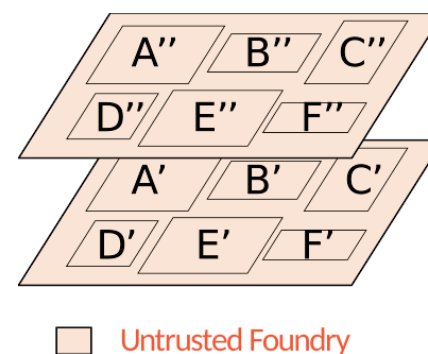
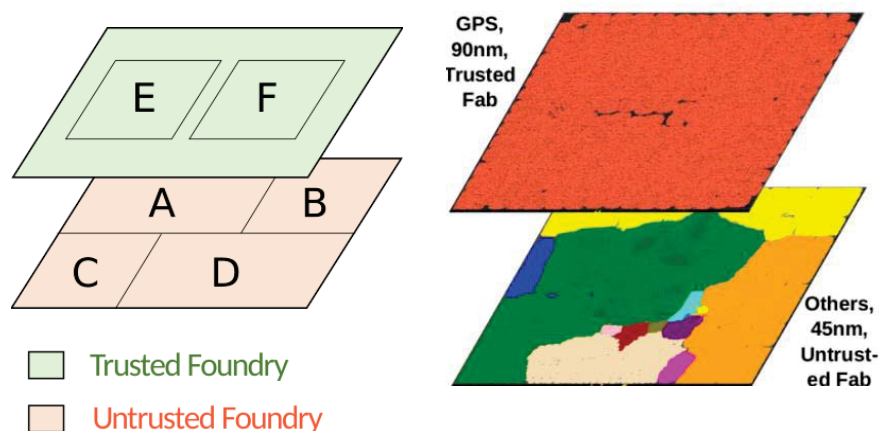
## Split Manufacturing with 2.5D and 3D Integration

- **Practical:** FEOL and BEOL processing uninterrupted for separate dies
- **Flexible:** system-level splitting into trusted versus untrusted dies/layers



## Split Manufacturing with 2.5D and 3D Integration

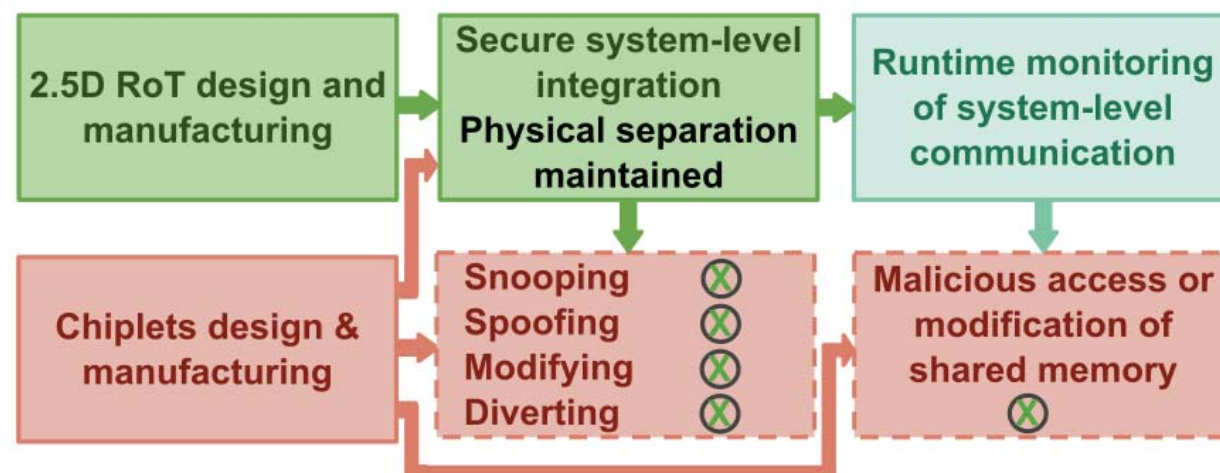
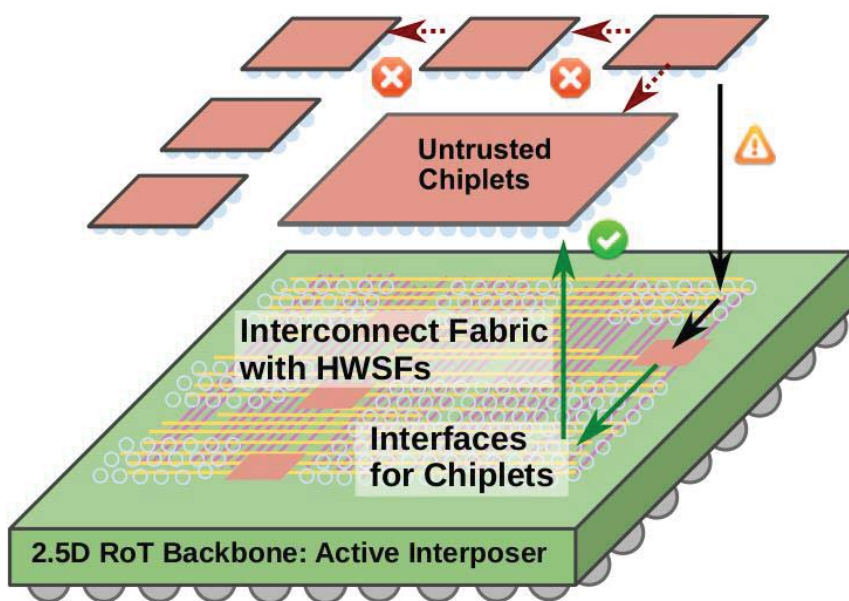
- **Practical:** FEOL and BEOL processing uninterrupted for separate dies
- **Flexible:** system-level splitting into trusted versus untrusted dies/layers
  - E.g., trusted interposer
  - E.g., F2F stacks: one trusted and one untrusted dies, heterogeneous integration; two untrusted dies, trusted RDL in between



Patnaik et al., TETC, 2019

## 2.5D and 3D Integration for Hardware Security: Root of Trust

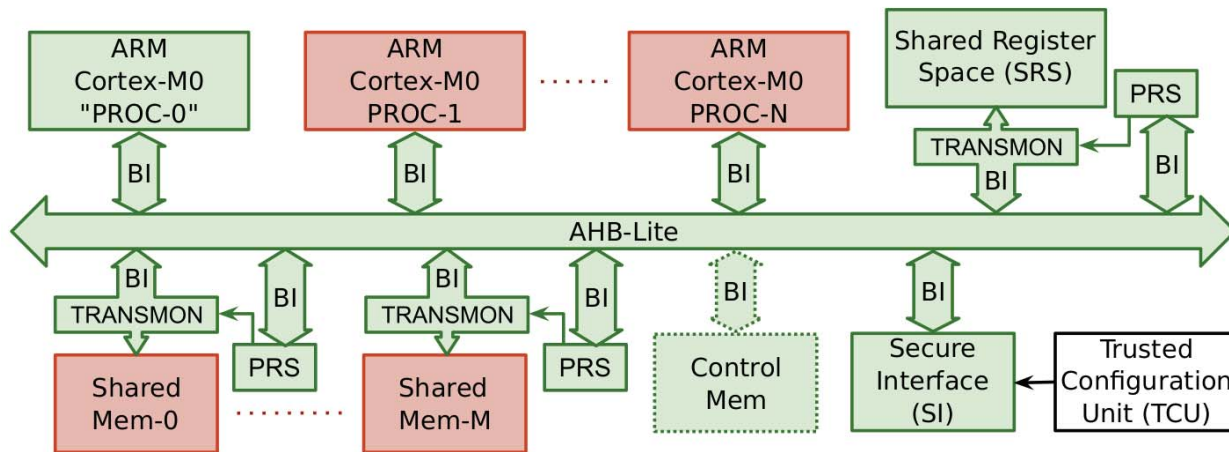
- **Physically secure** system-level integration and runtime monitoring of untrusted chips



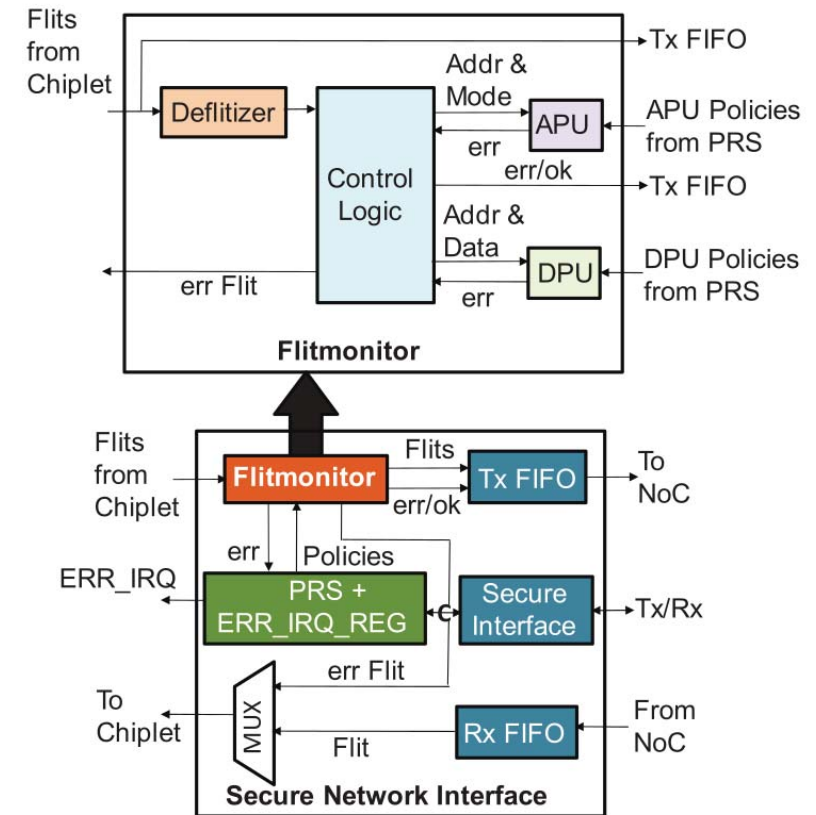
Nabeel et al., TC, 2020

# 2.5D and 3D Integration for Hardware Security: Root of Trust

- **Physically secure** system-level integration and runtime monitoring of untrusted chips
- Generic principle; demonstrated in an ARM w/ AHBL and a RISC-V w/ NoC architecture



Nabeel et al., TC, 2020

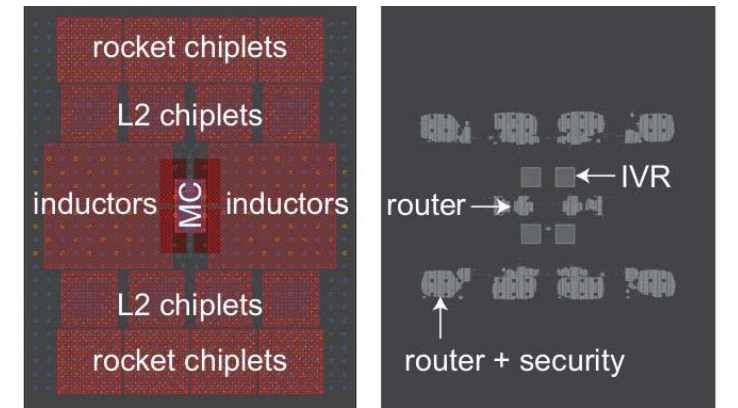
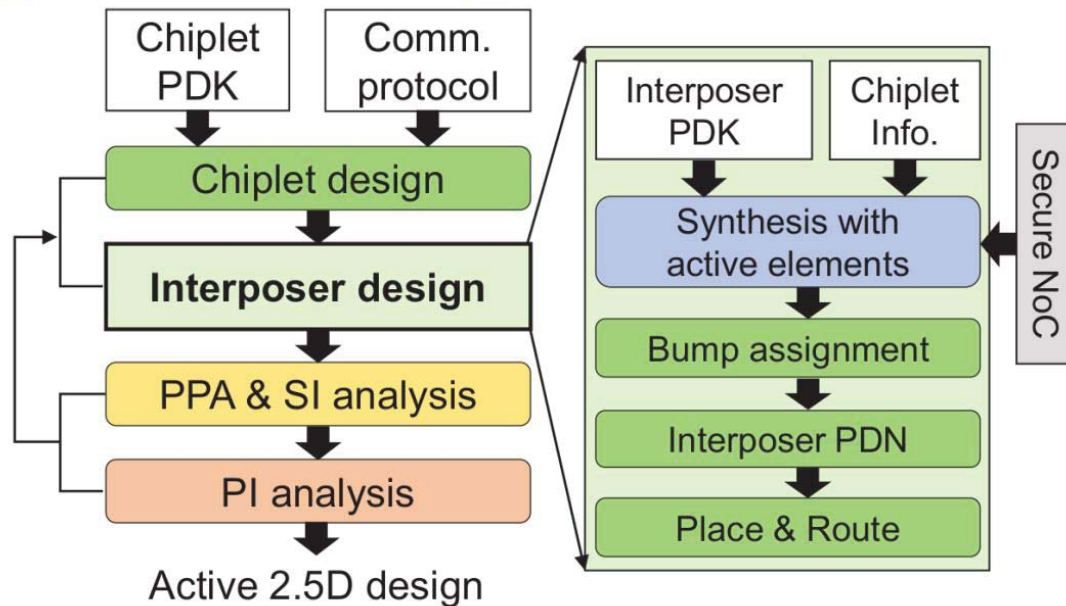


Park et al., TCPMT, 2020

## 2.5D and 3D Integration for Hardware Security: Root of Trust

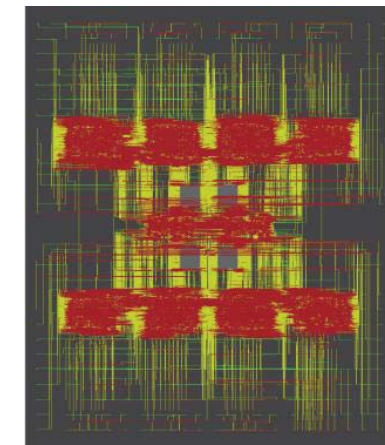
- **Physically secure** system-level integration and runtime monitoring of untrusted chips
- Security features easy to integrate in CAD flow

■ Synopsys DesignCompiler    ■ Synopsys PrimeTime    ■ Synopsys VCS  
■ Cadence Innovus    ■ Cadence Voltus



(c) floorplan

(d) interposer placement



(e) interposer routing

Park et al.,  
TCPMT, 2020

## Hardware Security for and beyond CMOS Technology: Challenges

- Hardware security relies on technology exploration, device characterization, circuit design, architectures, etc.
  - CAD support for security schemes as well as emerging technologies is essential
- Closer interaction between communities: security, technology, CAD
  - Joint (re-)definition and application of security metrics across the stack
  - Joint (re-)consideration of threat models
  - Technology exploration with early focus on security, not as after-thought
- Most emerging technologies are CMOS compatible/hybrid
  - System-level identification of “weakest link” in security scheme

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Thank you!

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